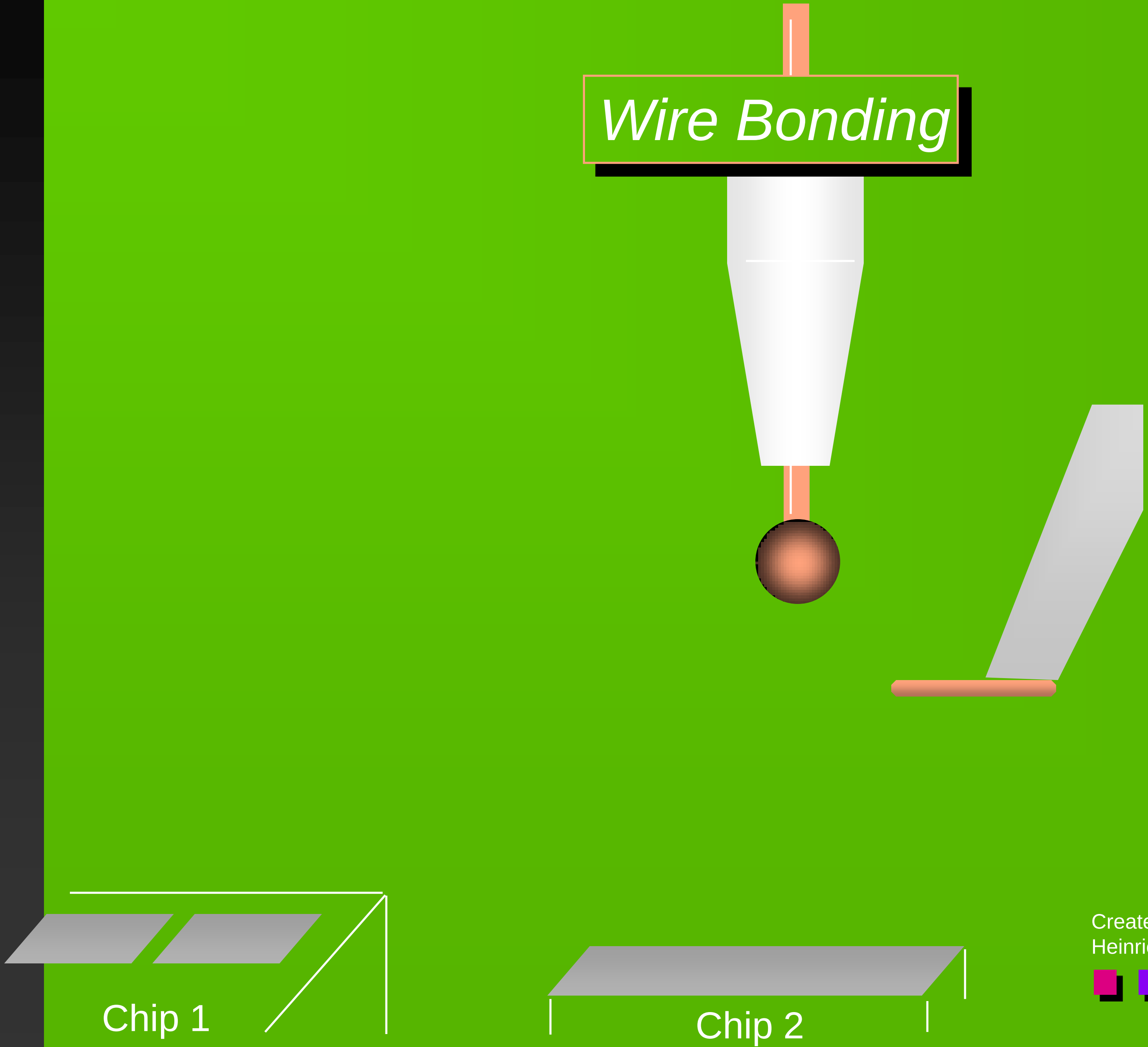
Wire Bonding

ESEC



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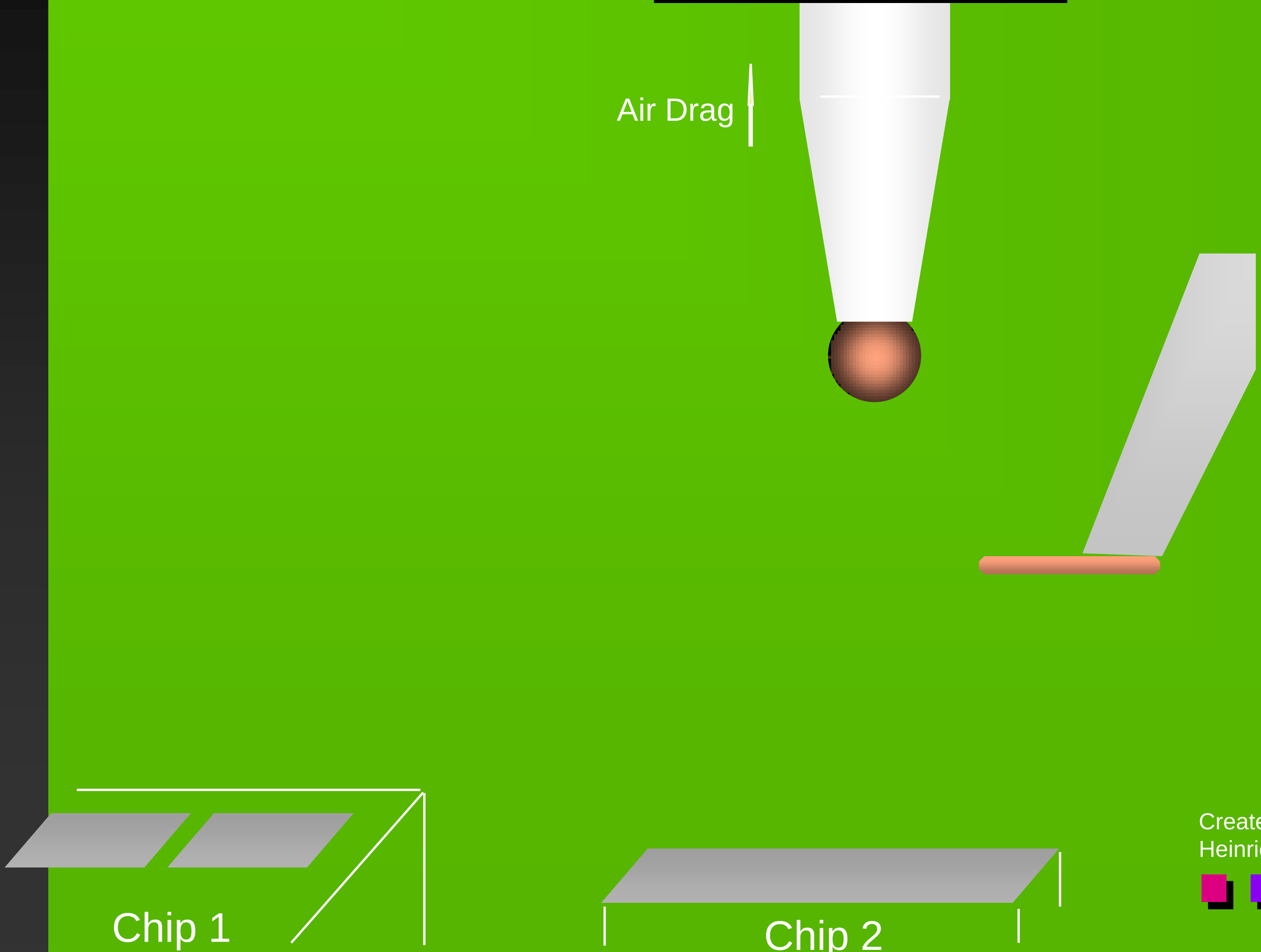
Wire Bonding

ESEC



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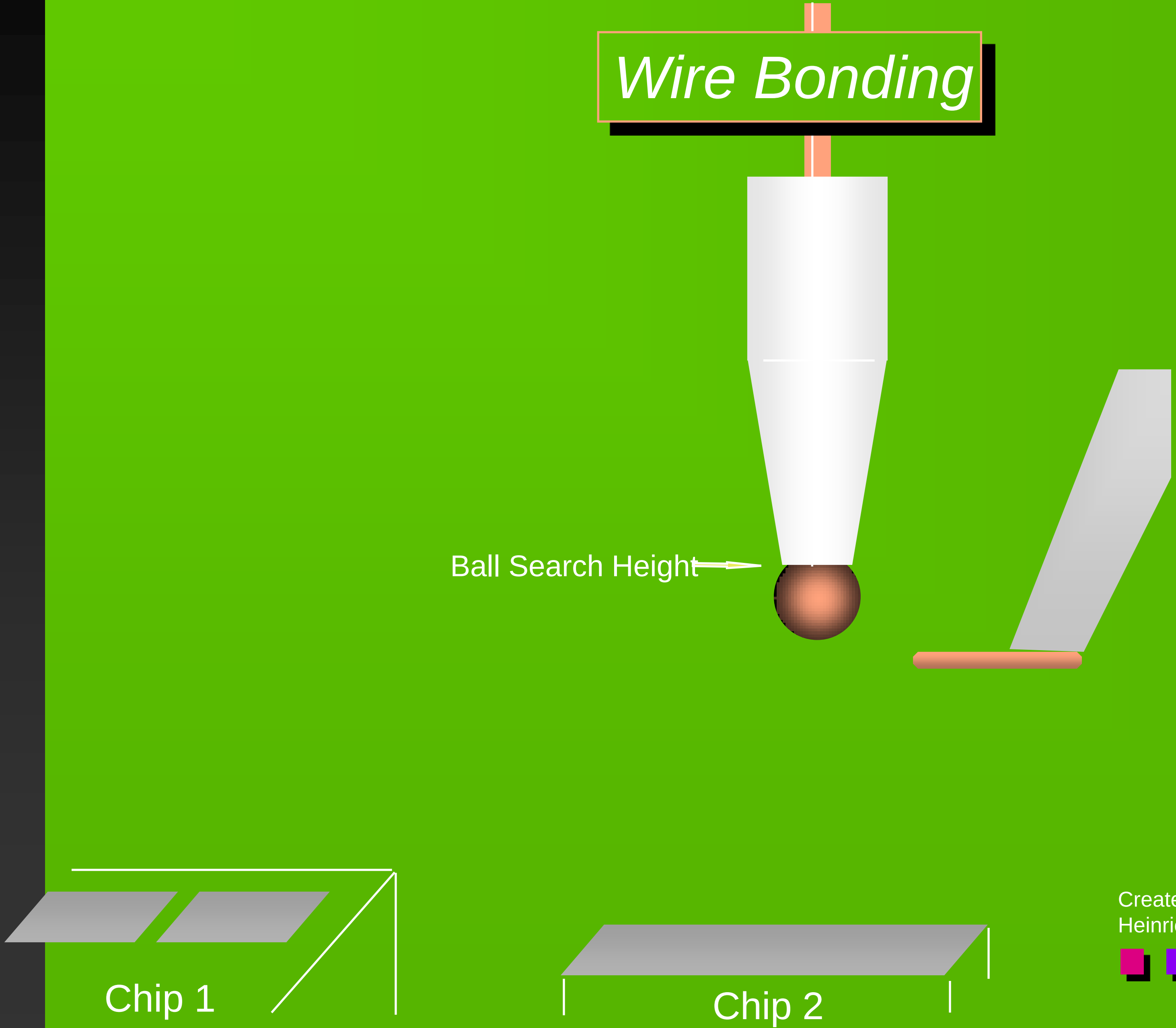
Wire Bonding

ESEC



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Wire Bonding

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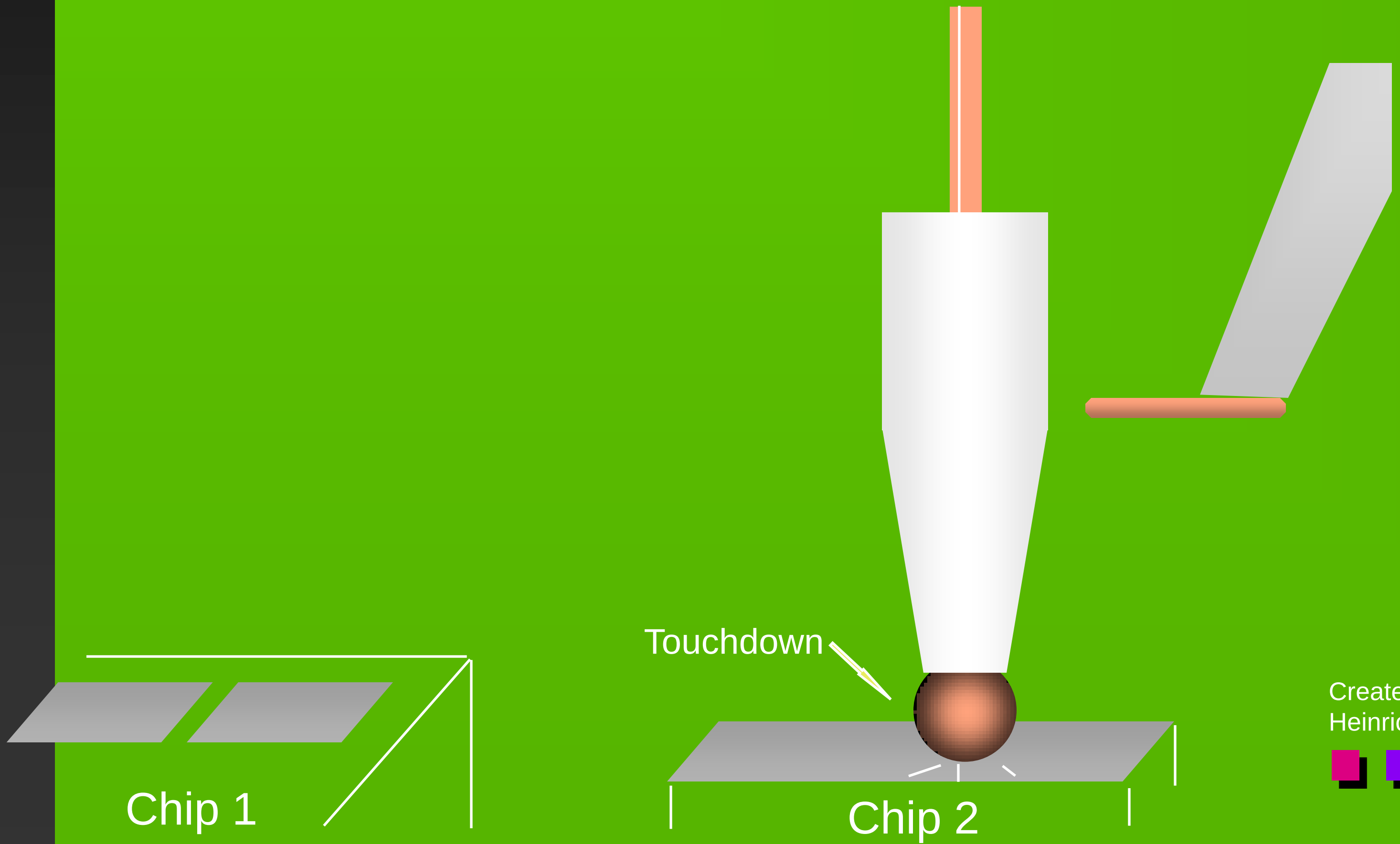

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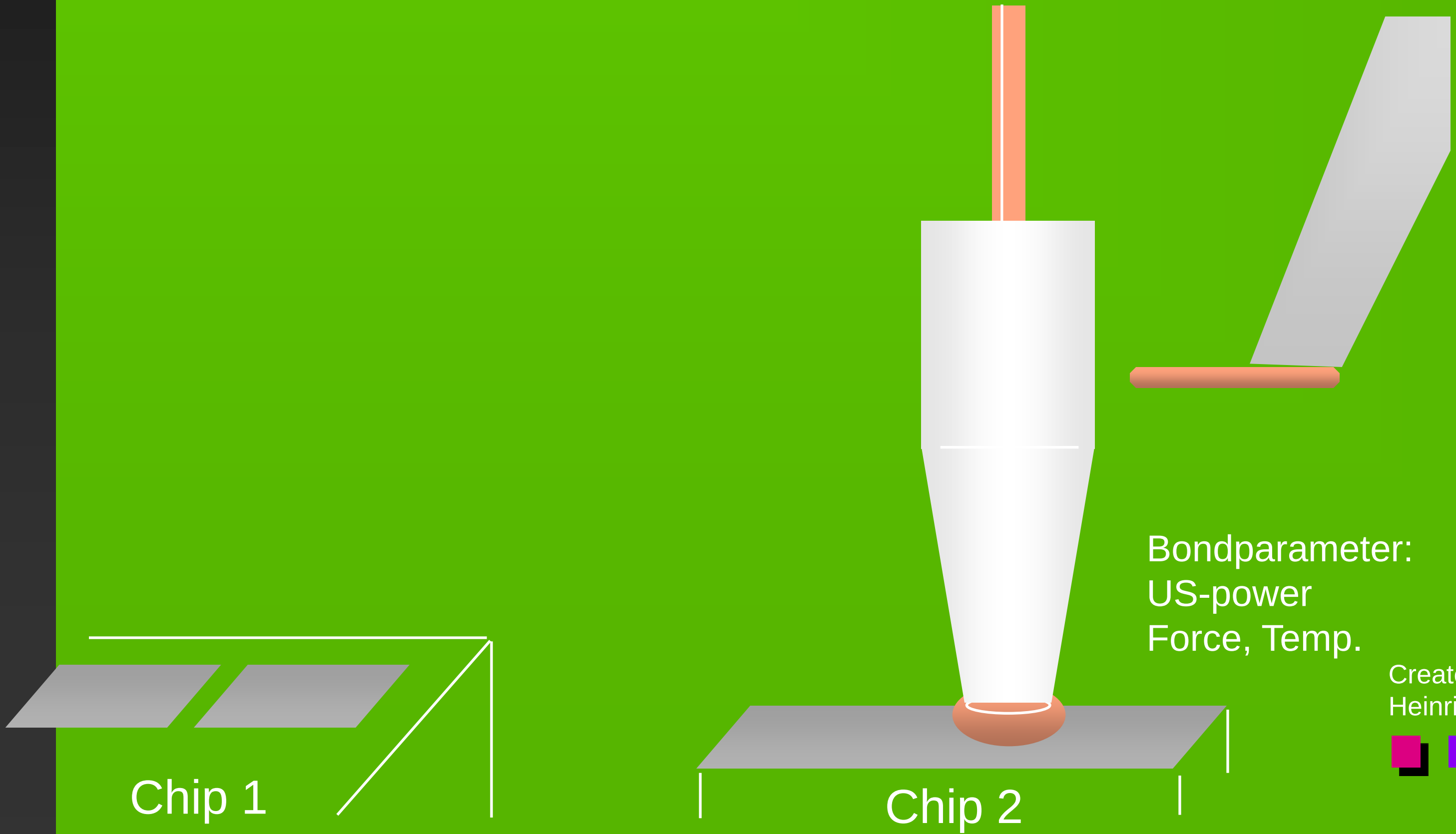

Bondparameter:
US-power
Force, Temp.

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Wire Bonding

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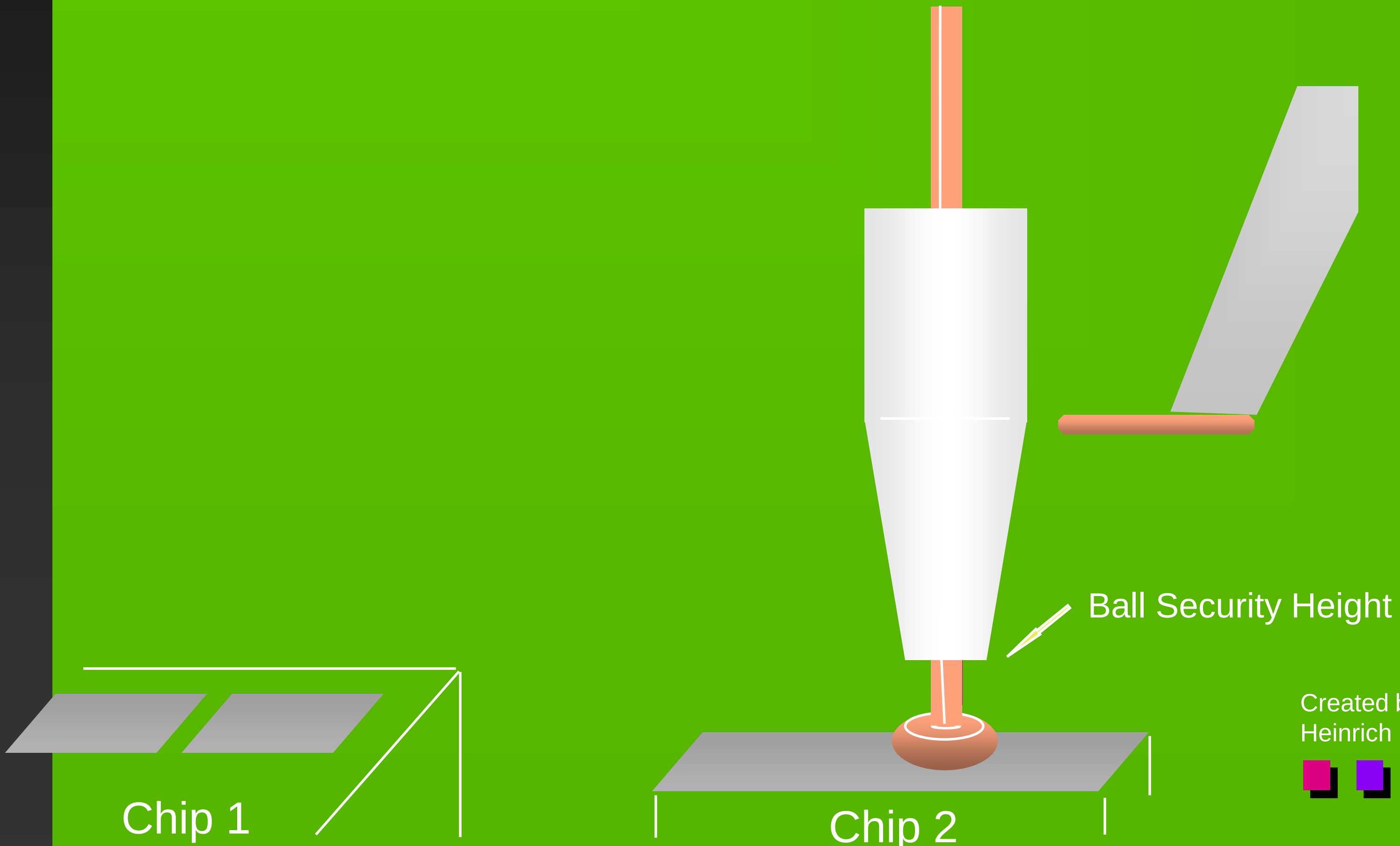

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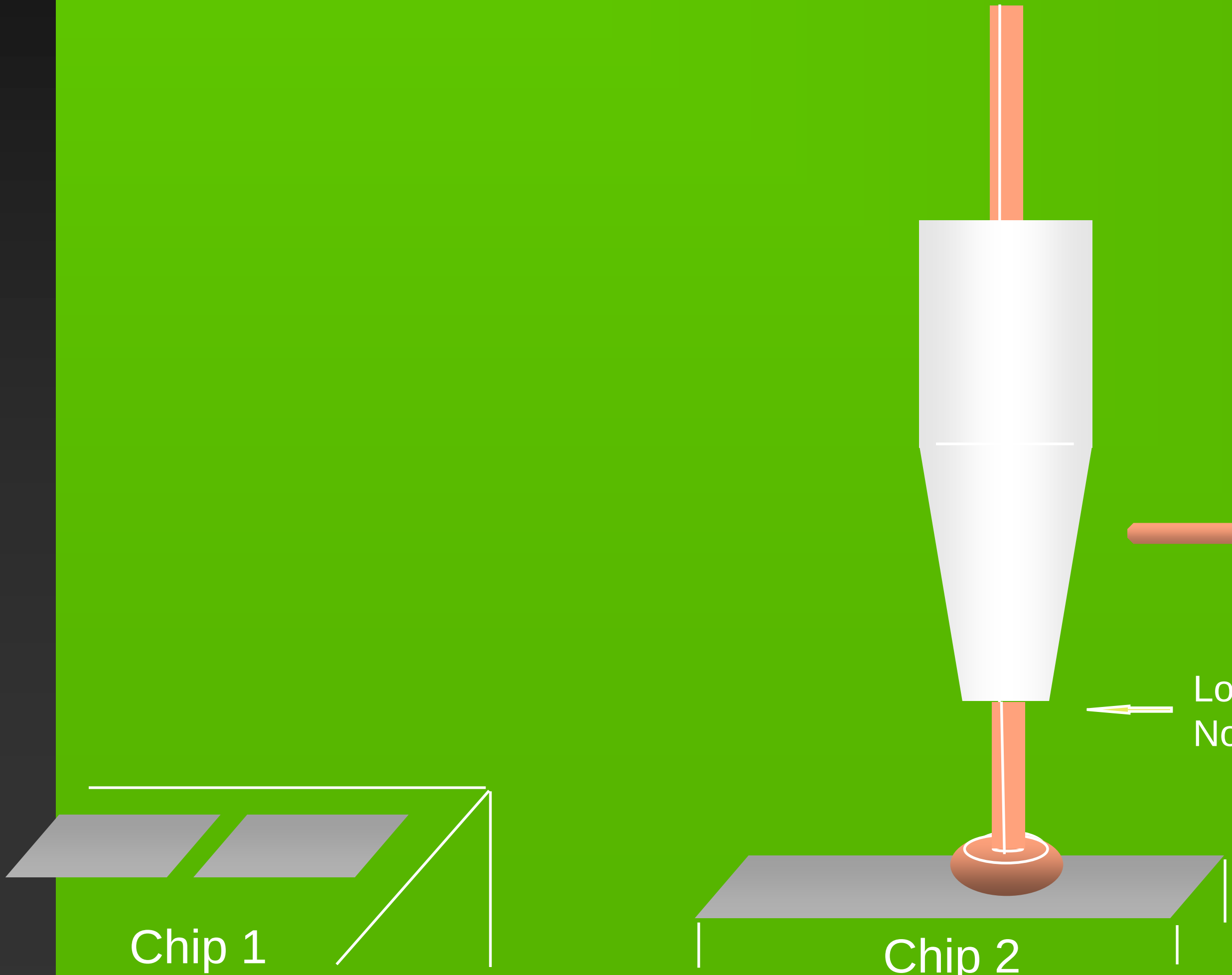

Looping for Bump:
No reverse loop is required !

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Wire Bonding

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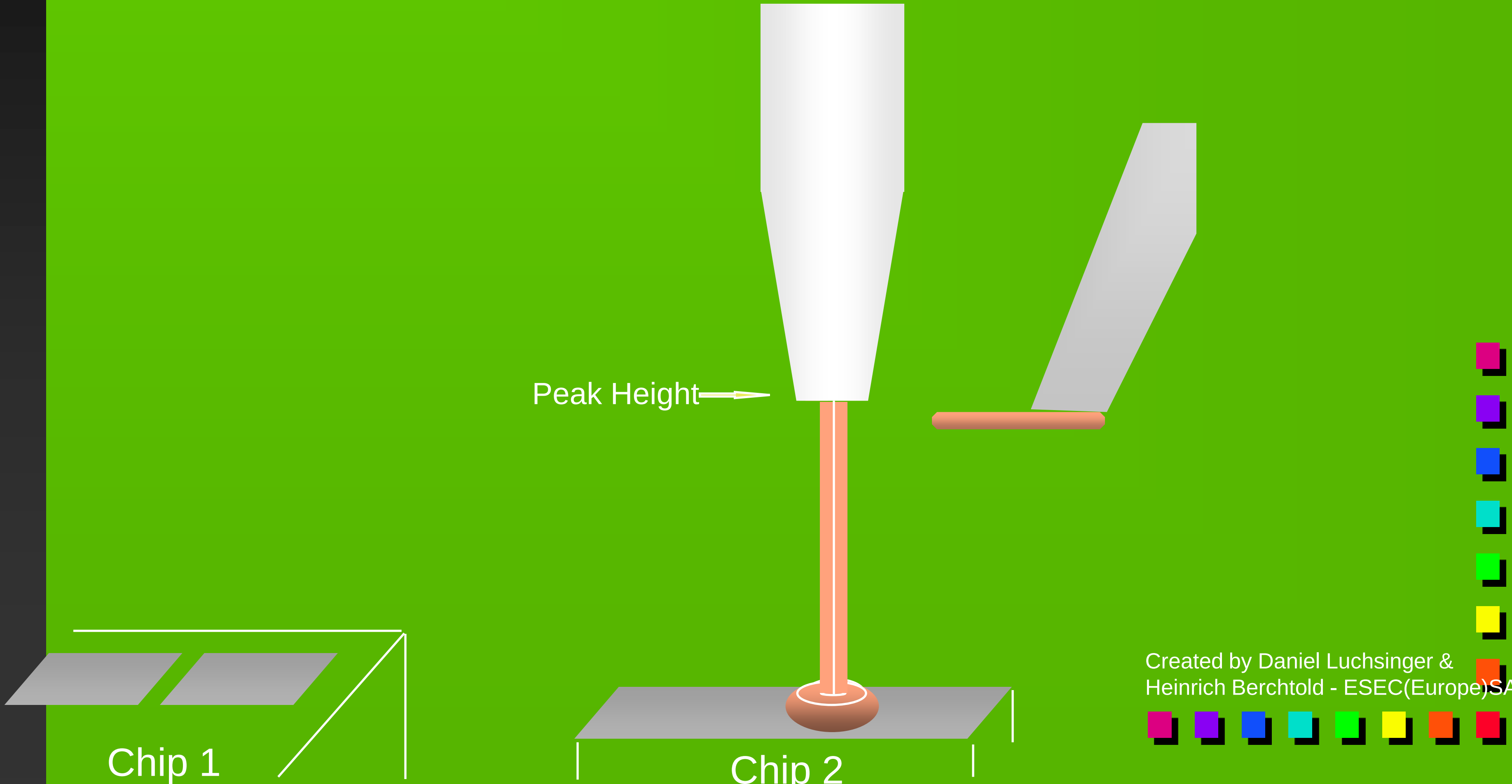

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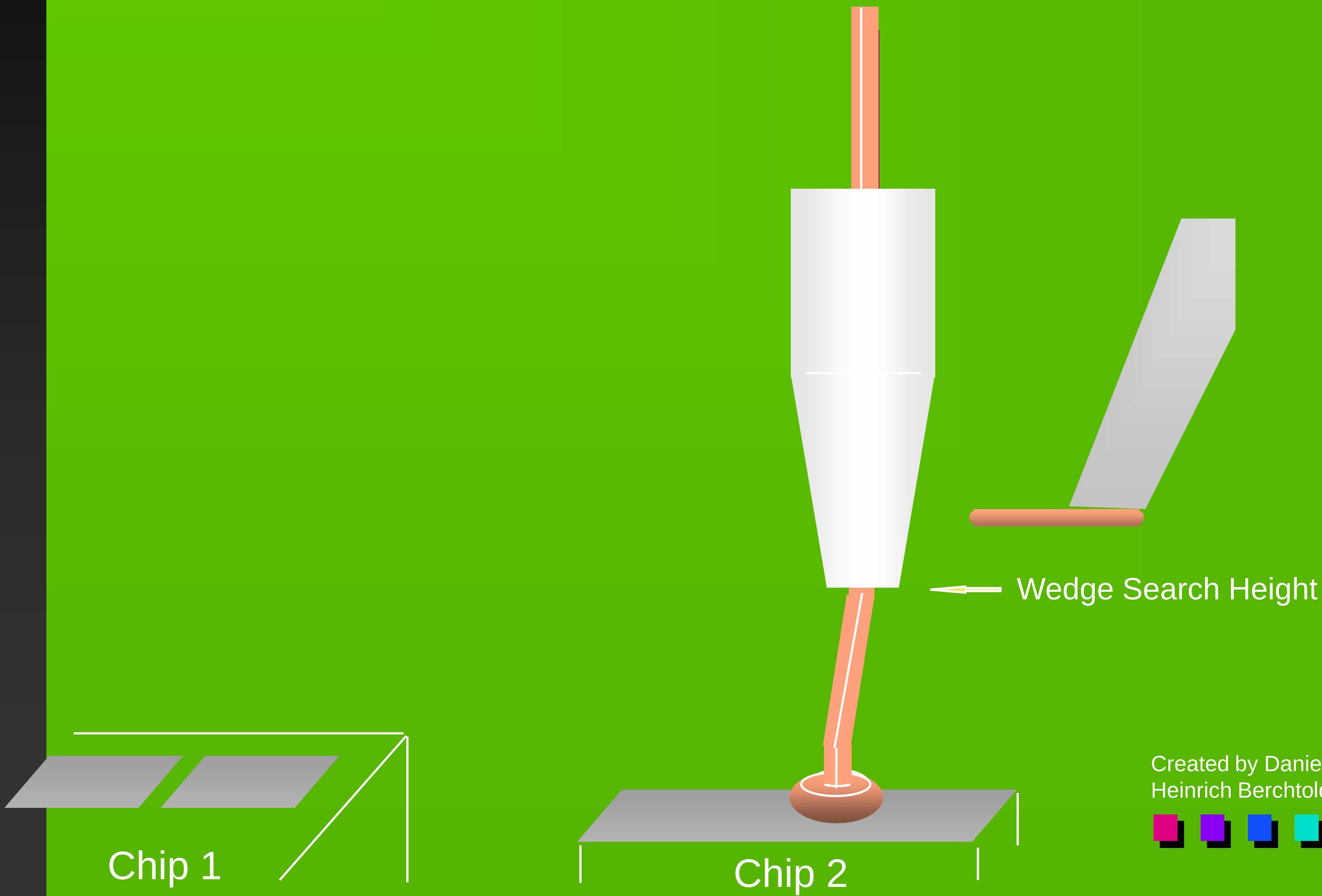

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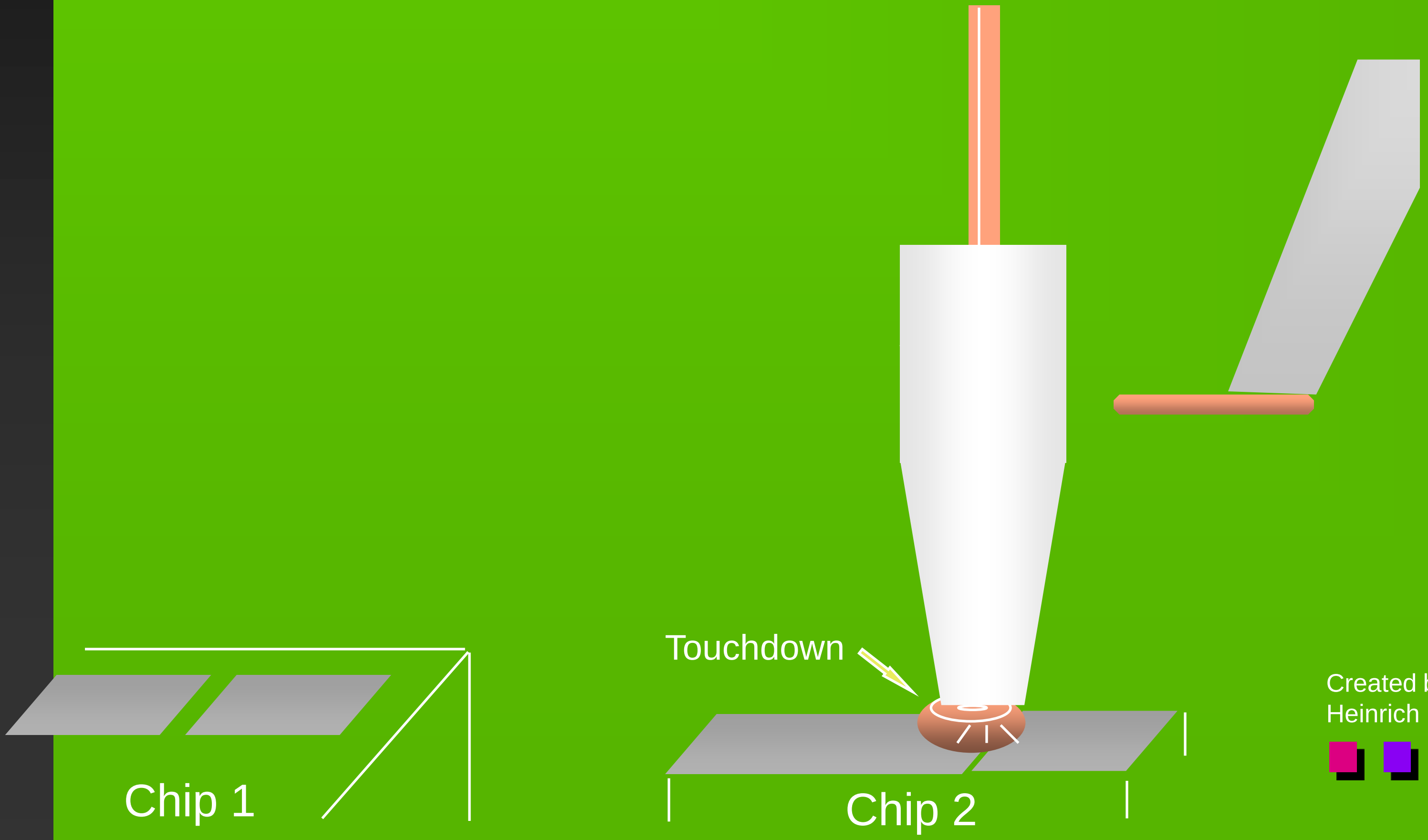

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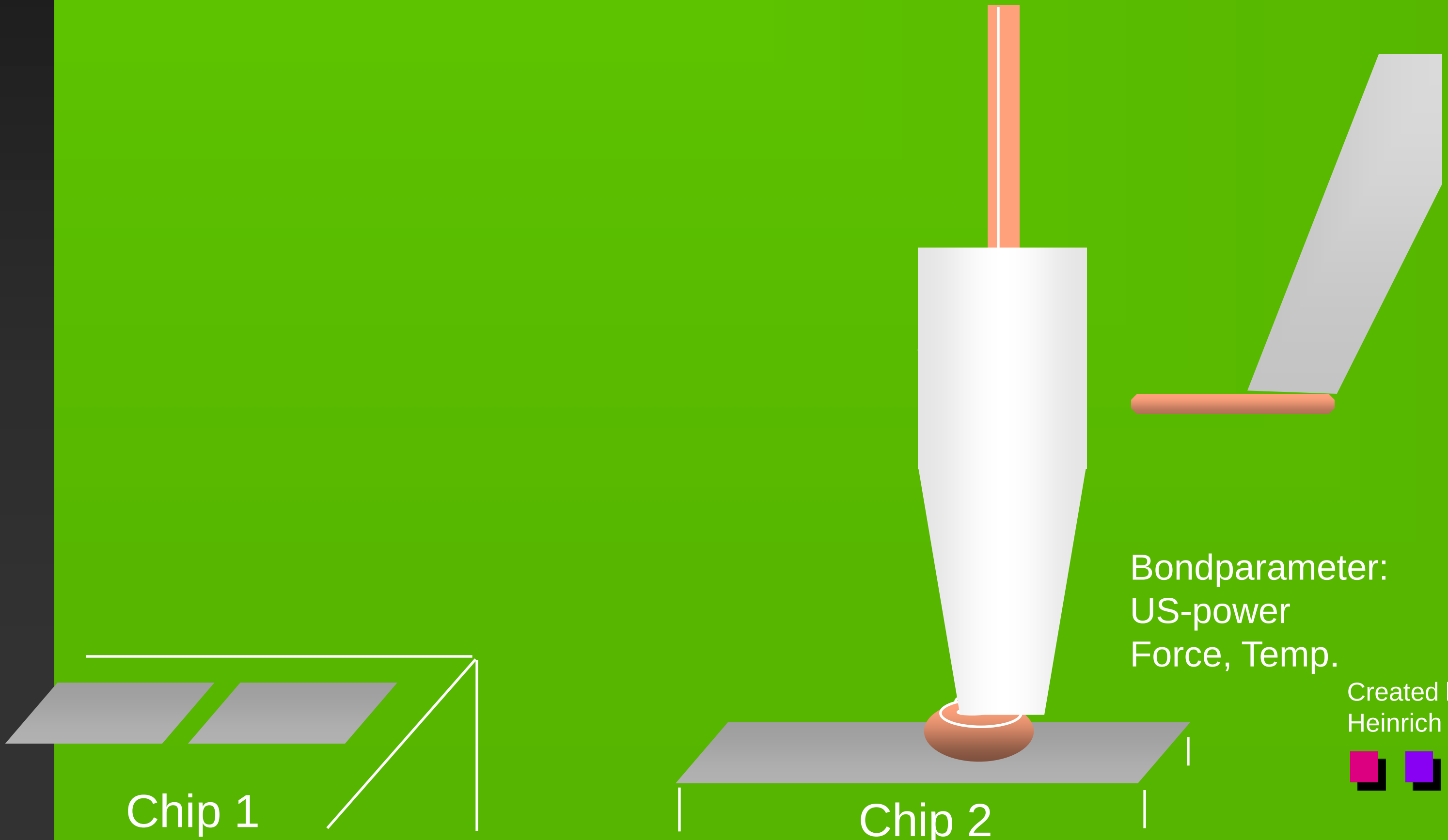

Bondparameter:
US-power
Force, Temp.

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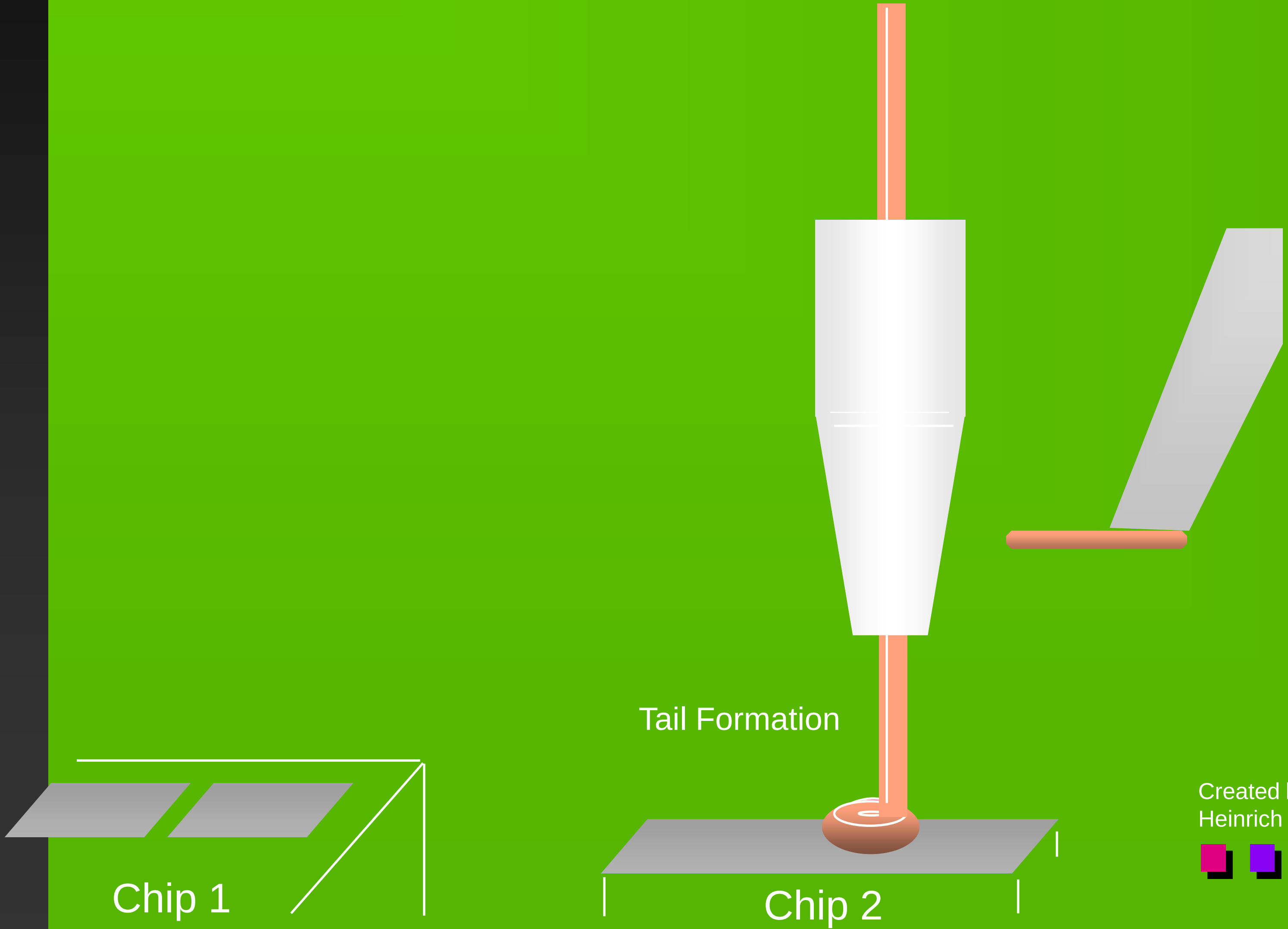

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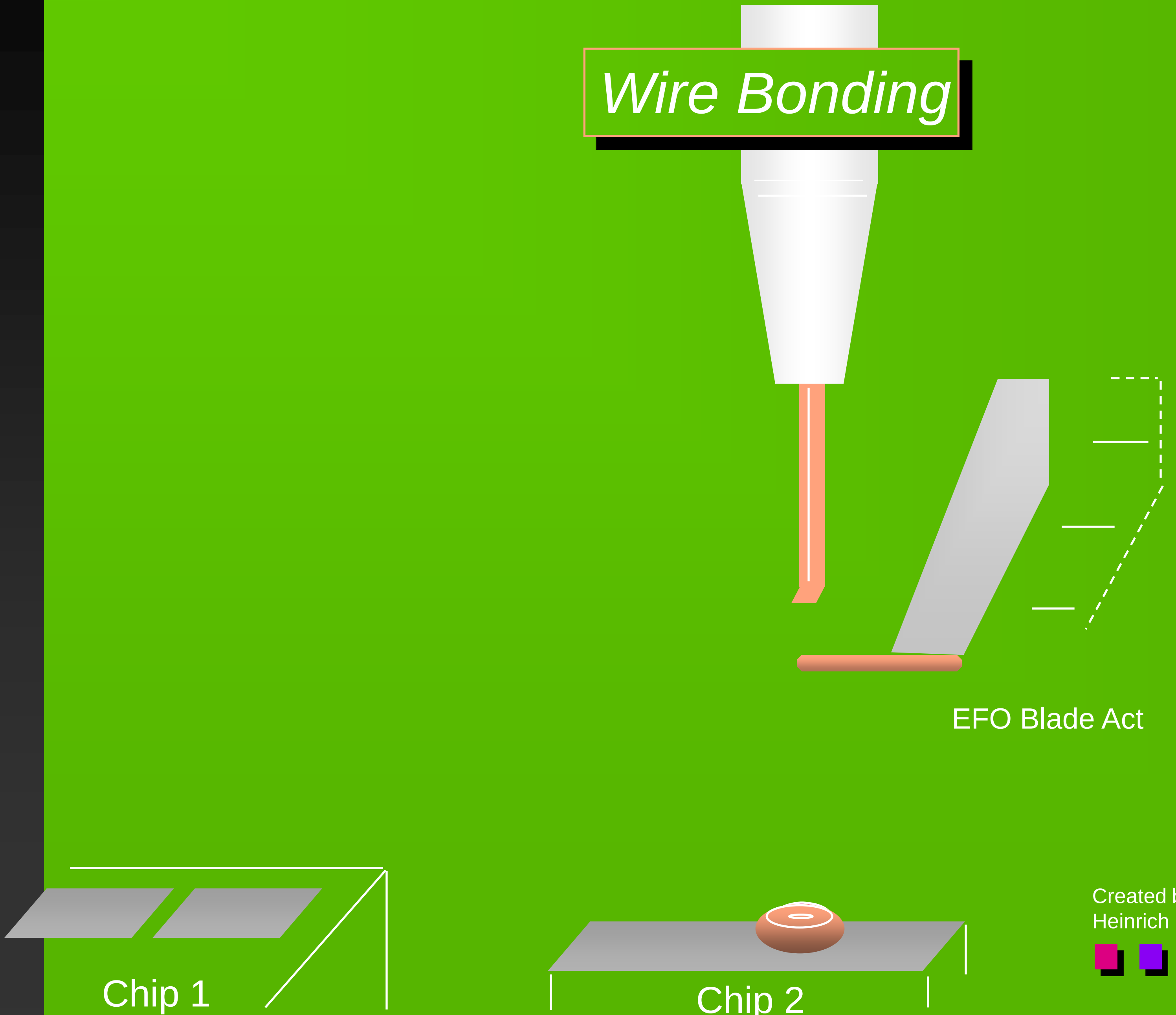

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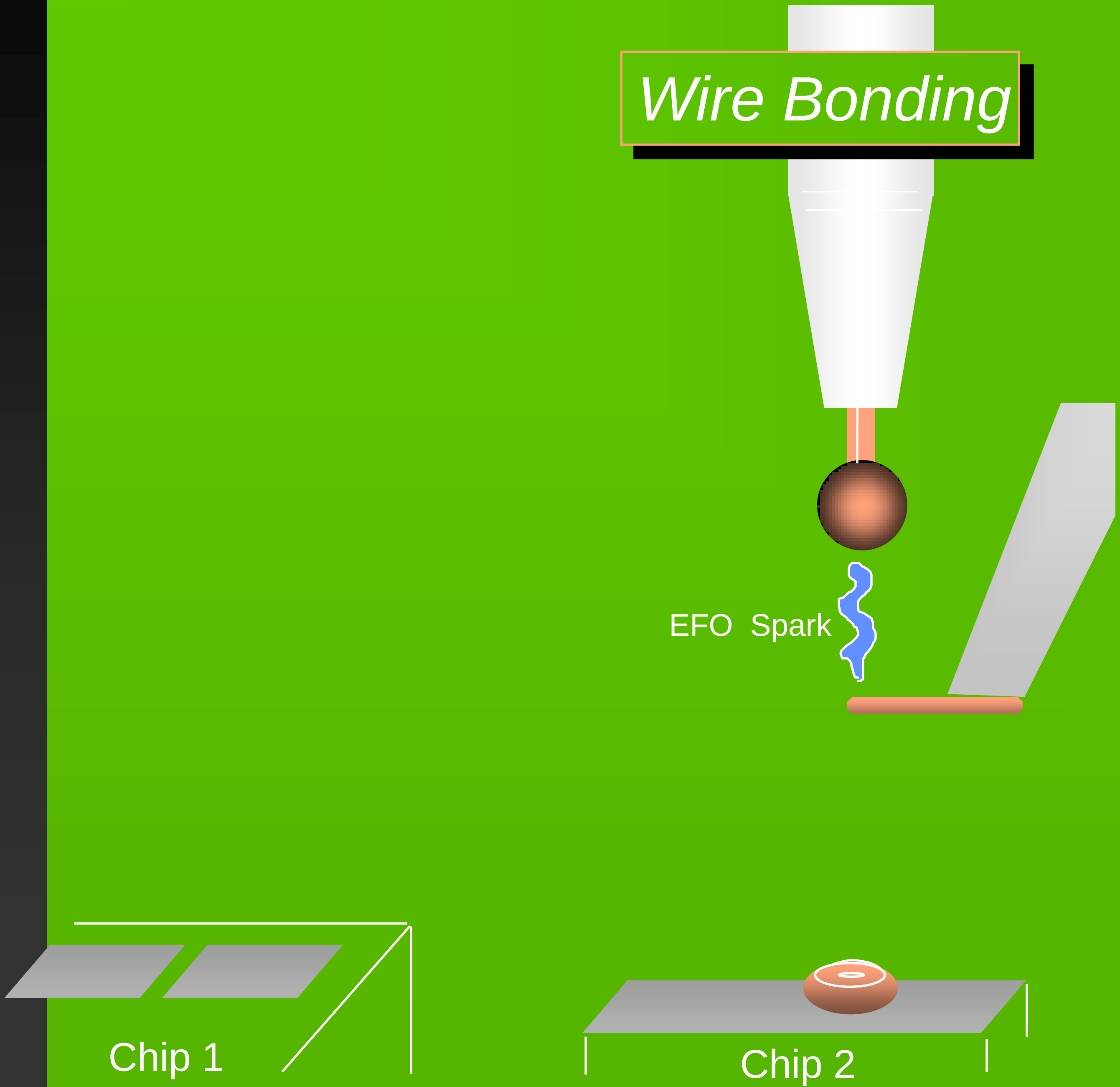

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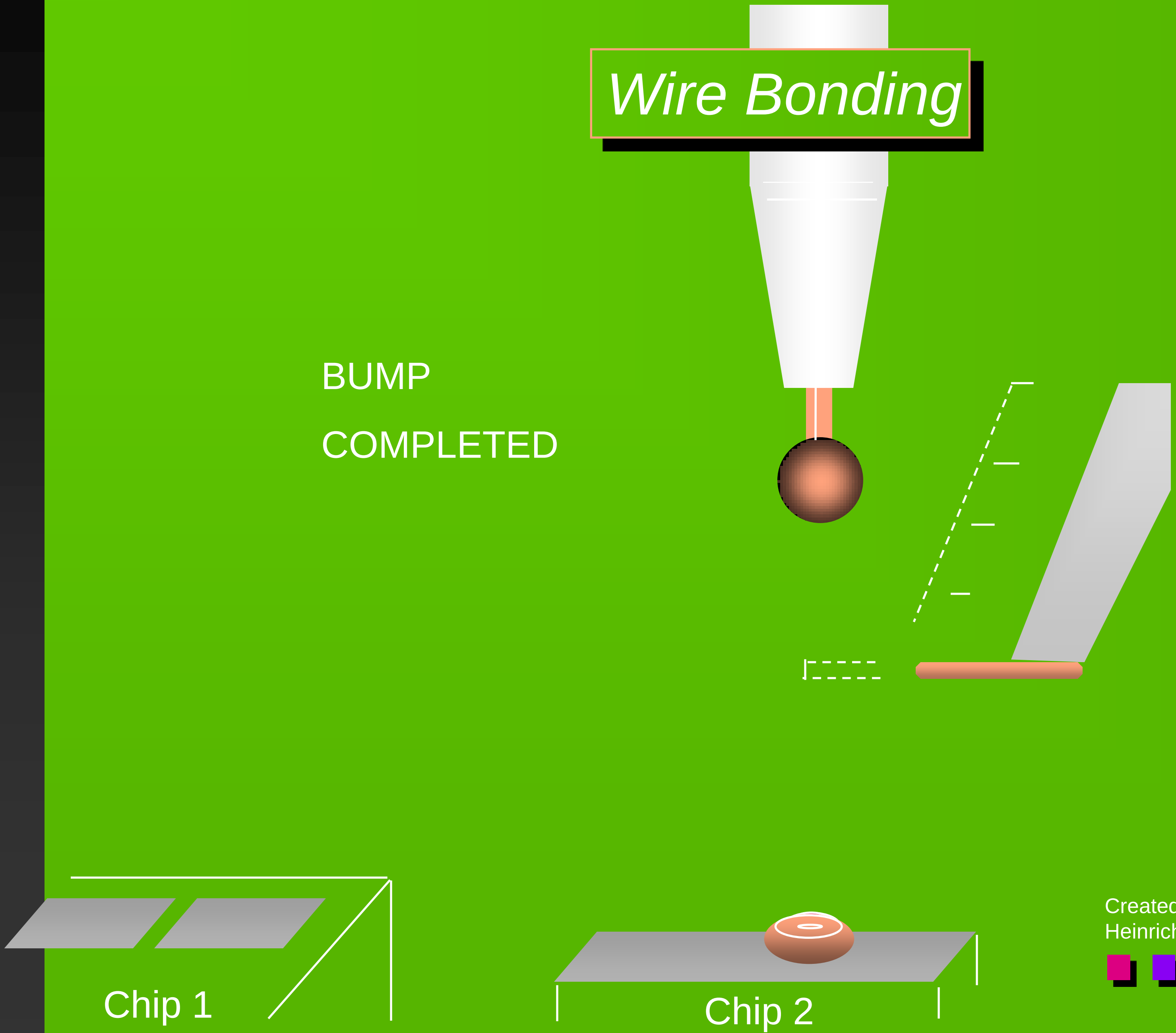
ESEC



BUMP

COMPLETED

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Wire Bonding

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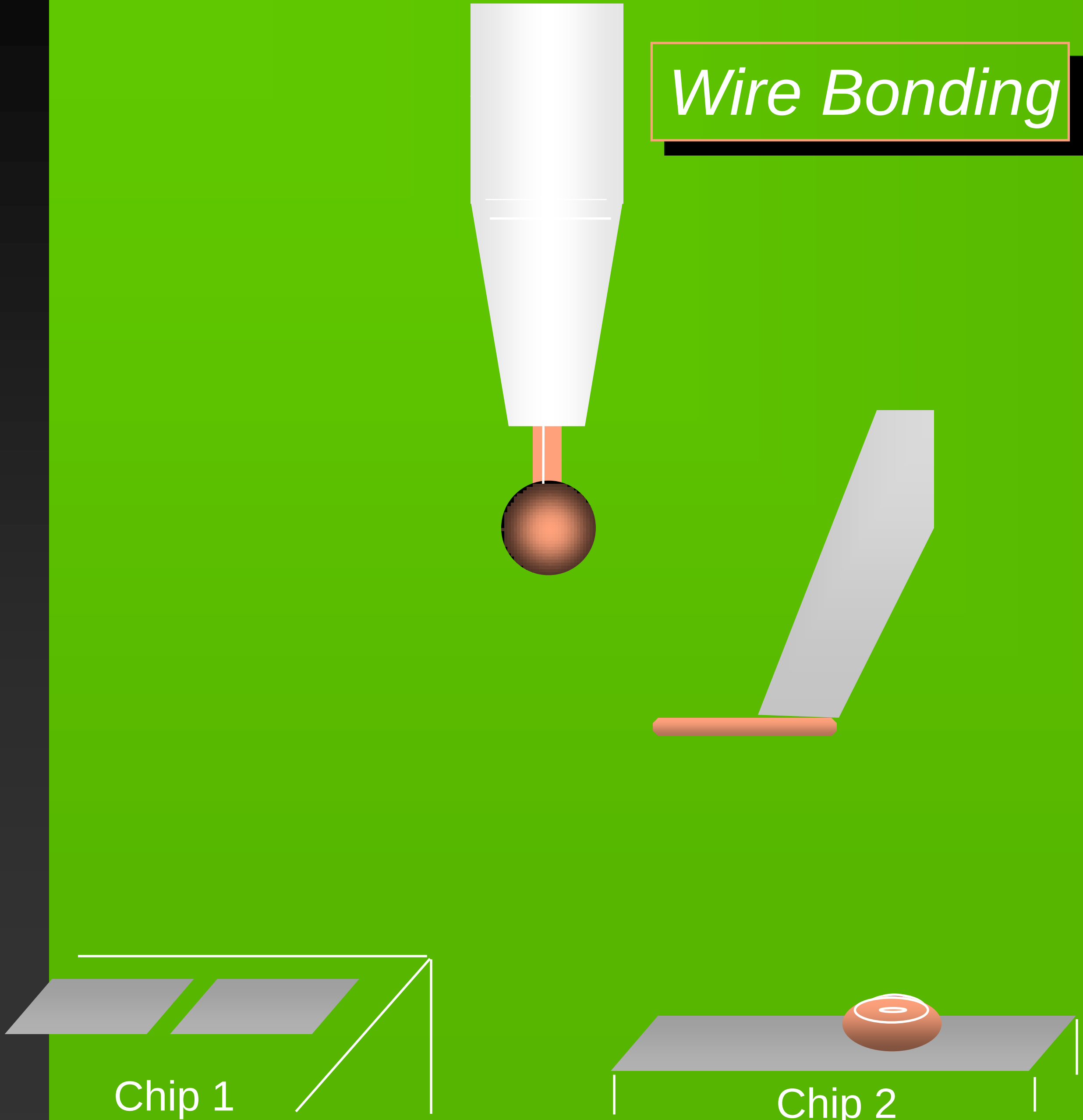

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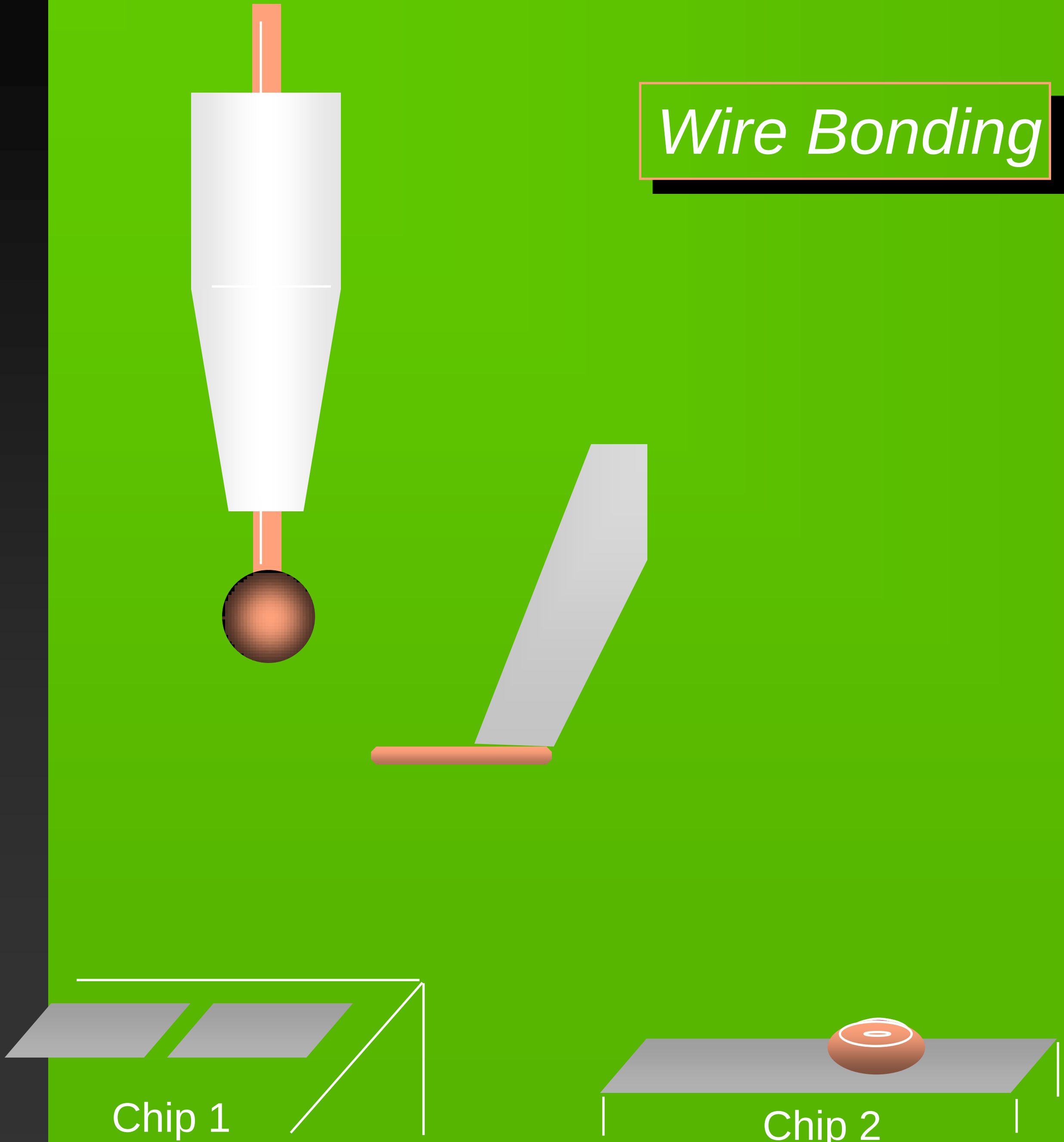

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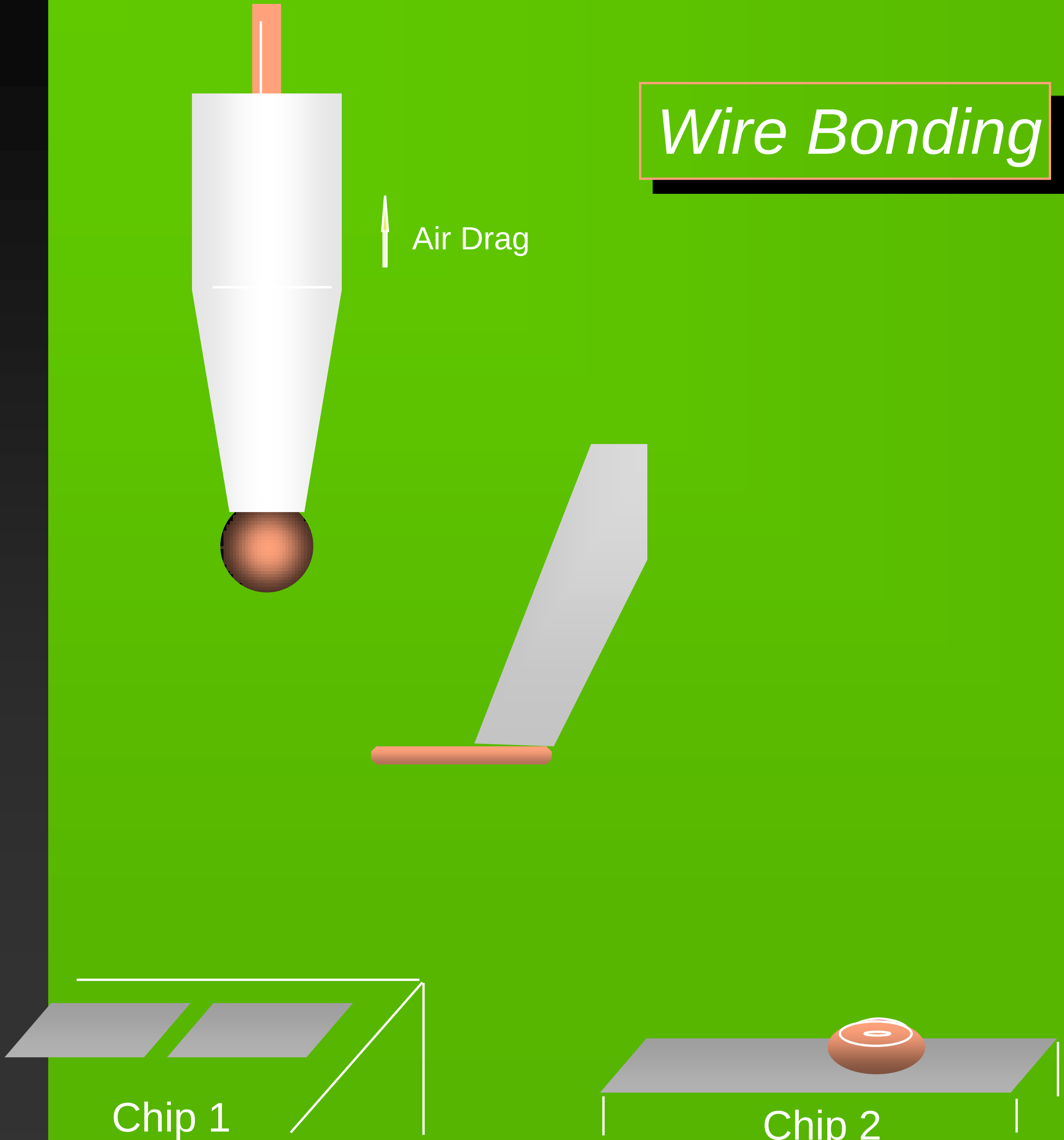

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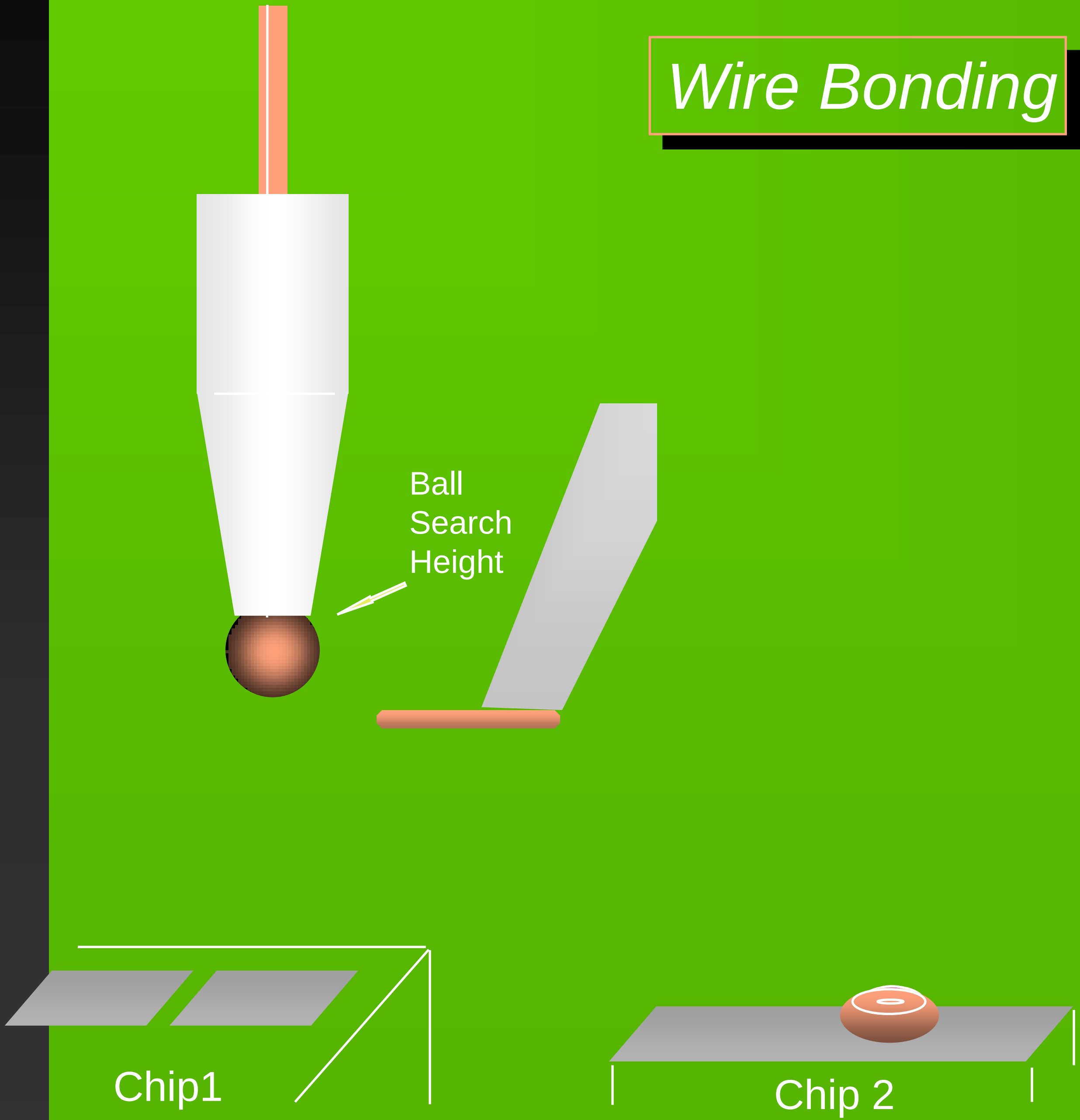

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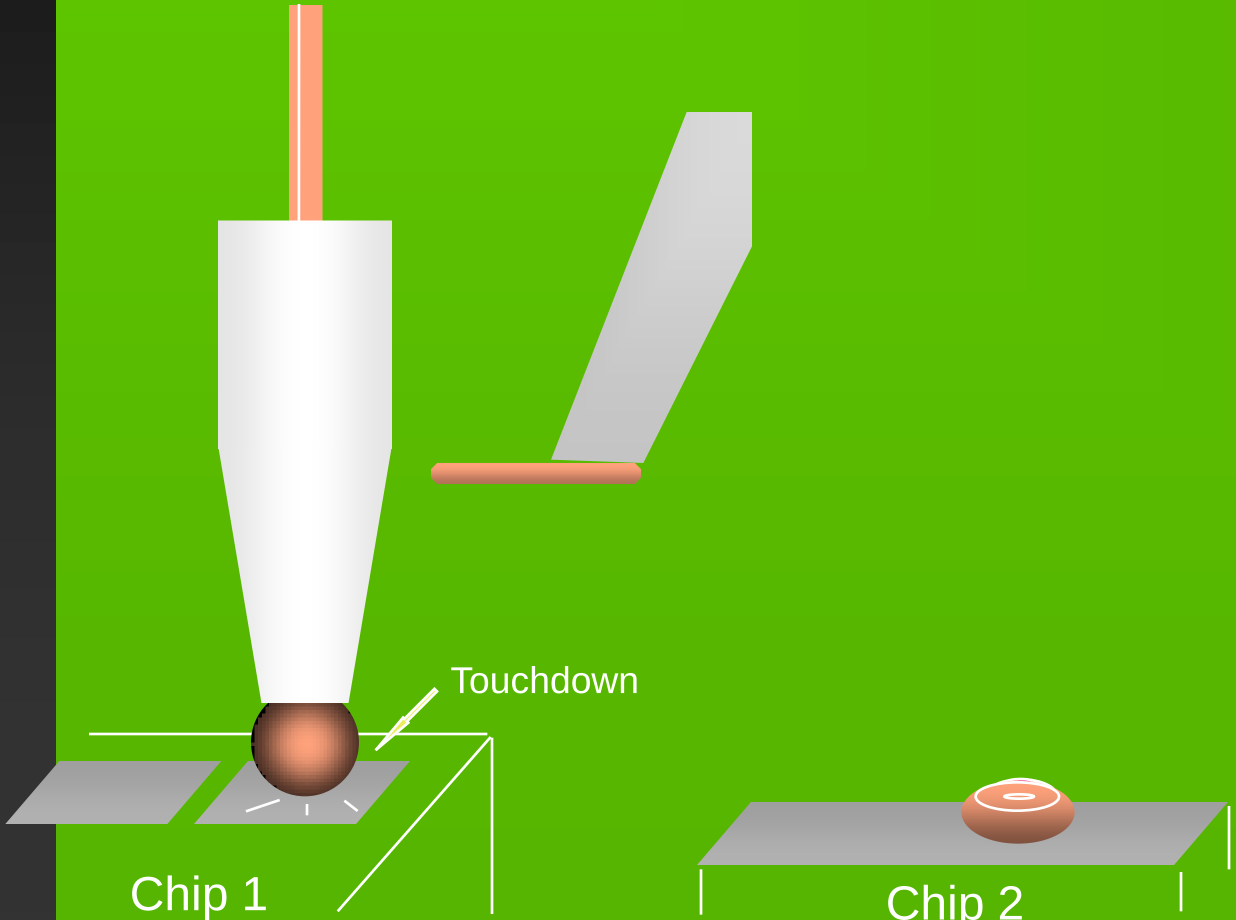

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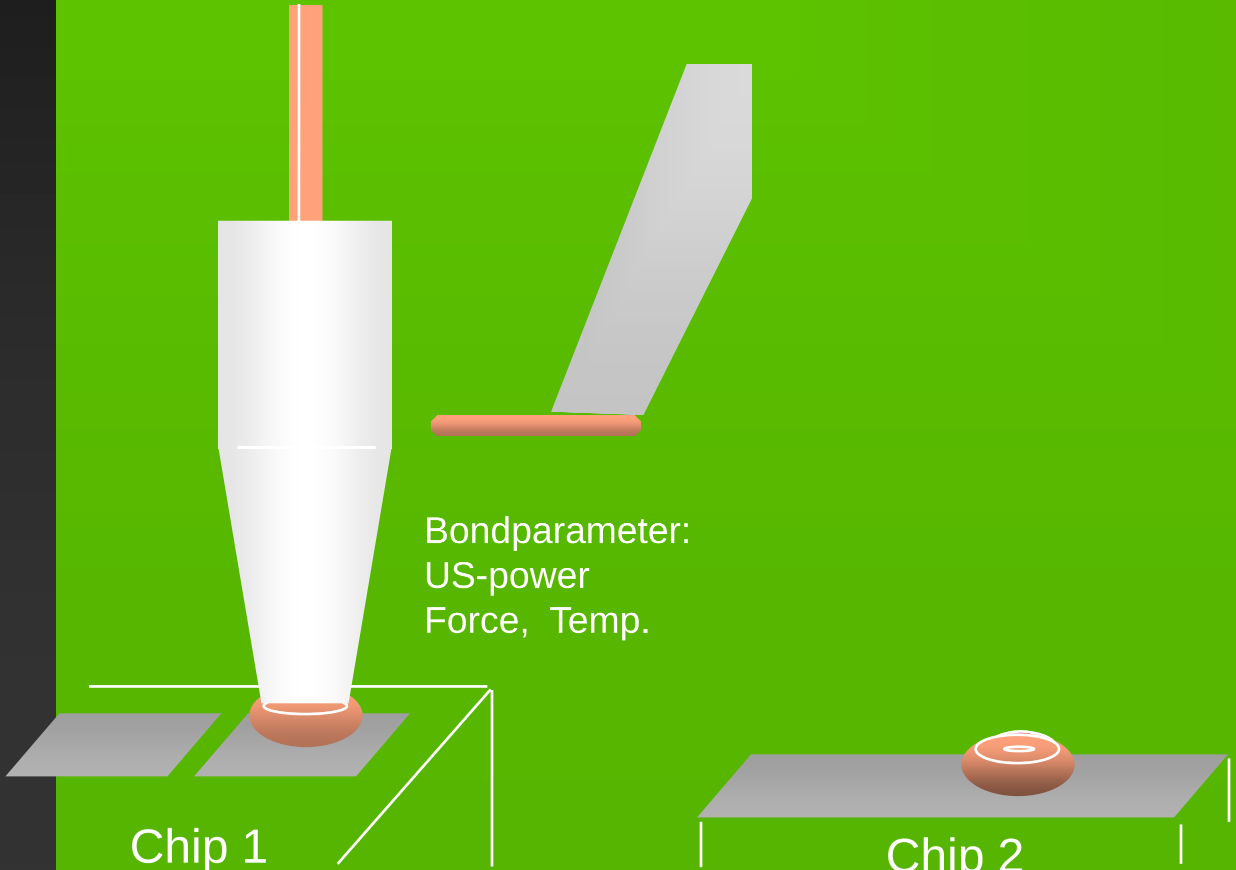

Bondparameter:
US-power
Force, Temp.

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Wire Bonding

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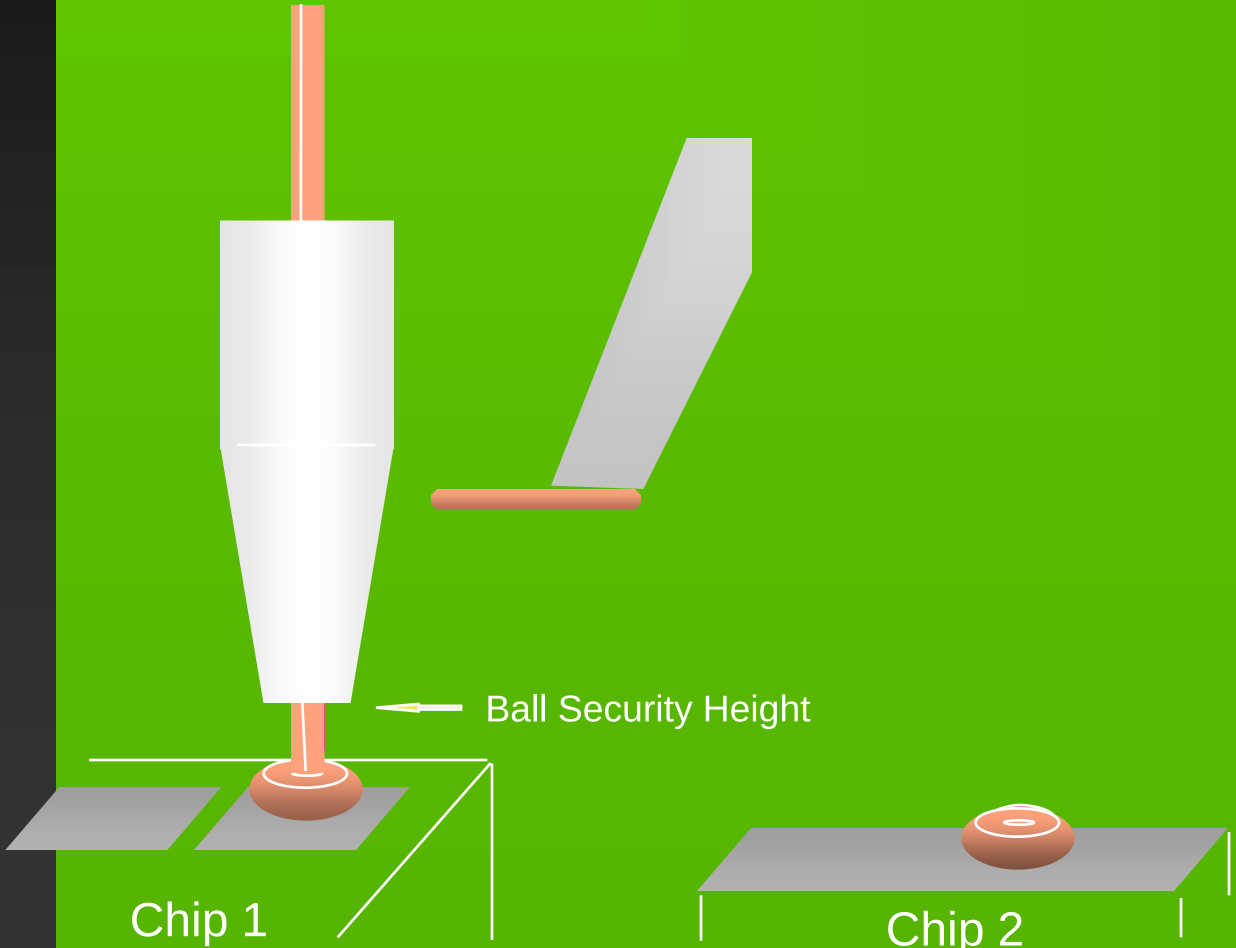

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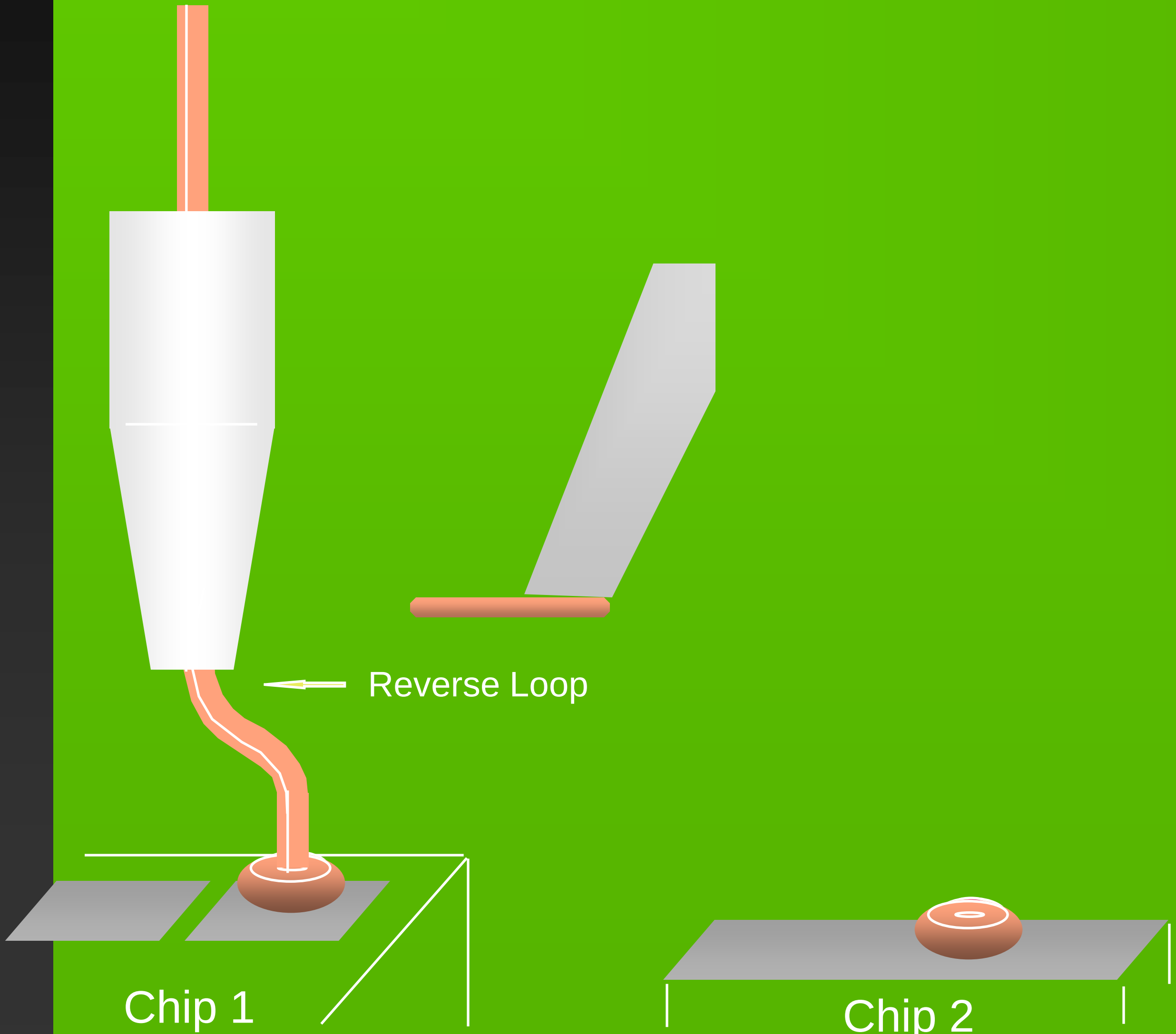

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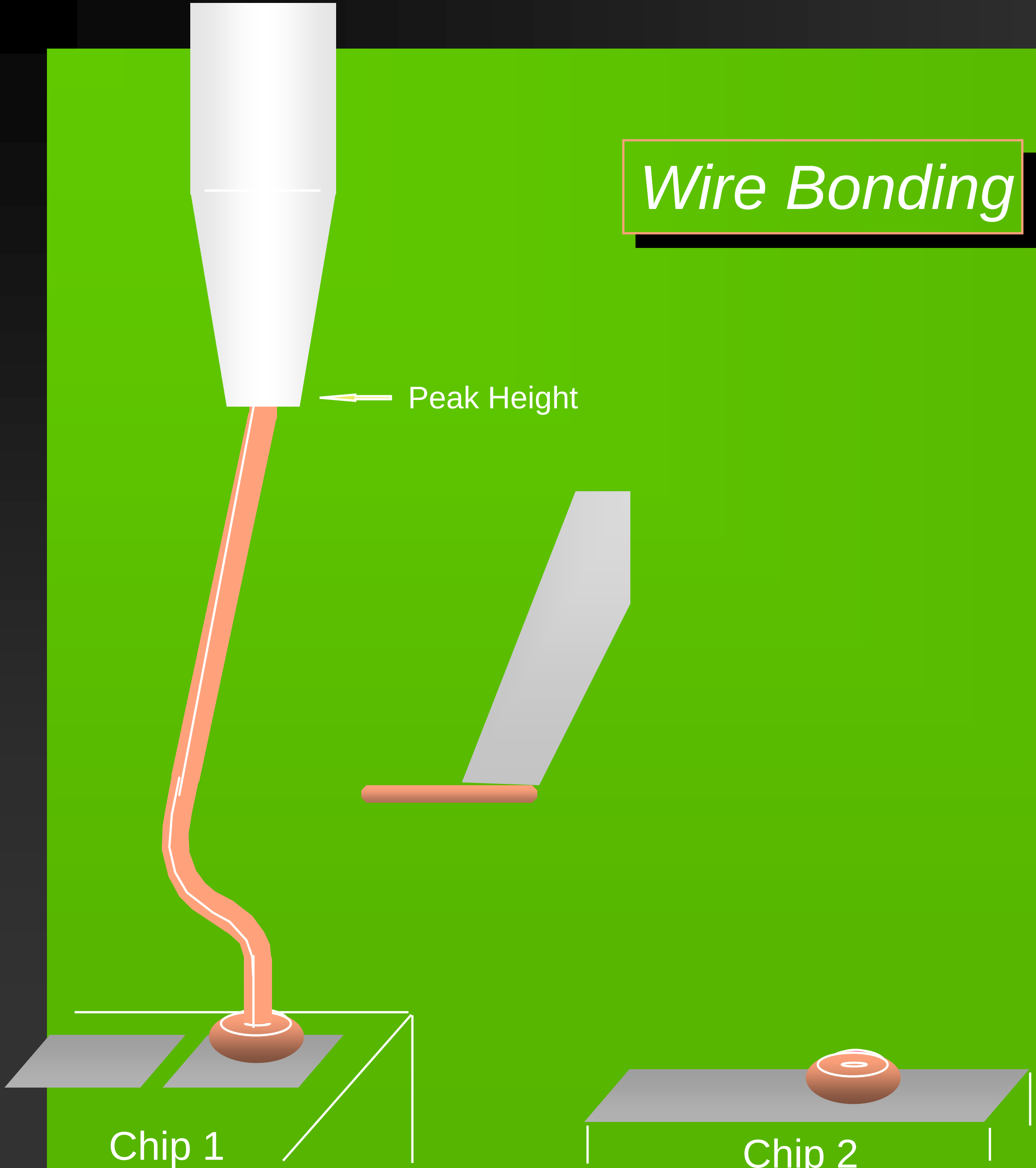

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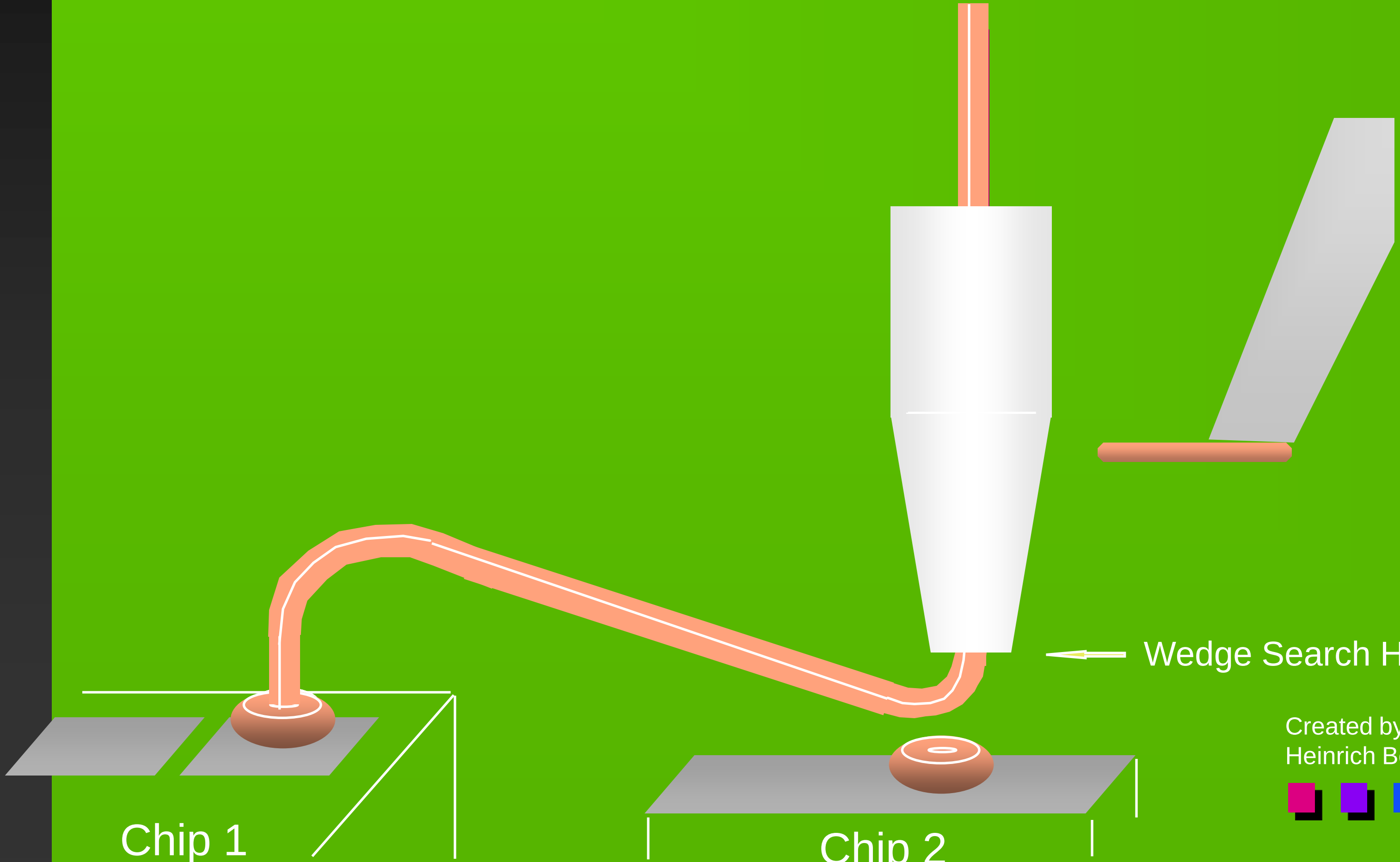

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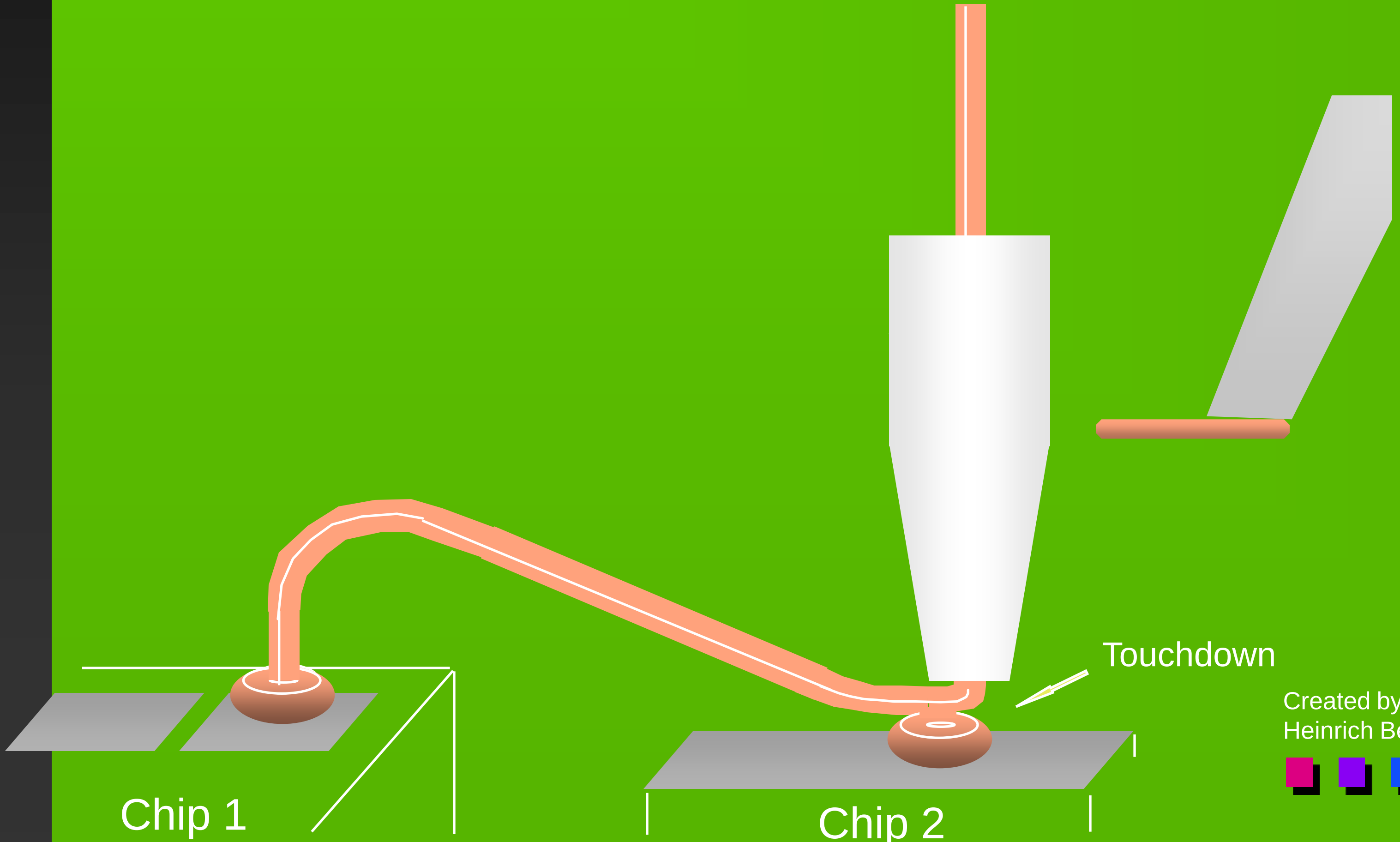

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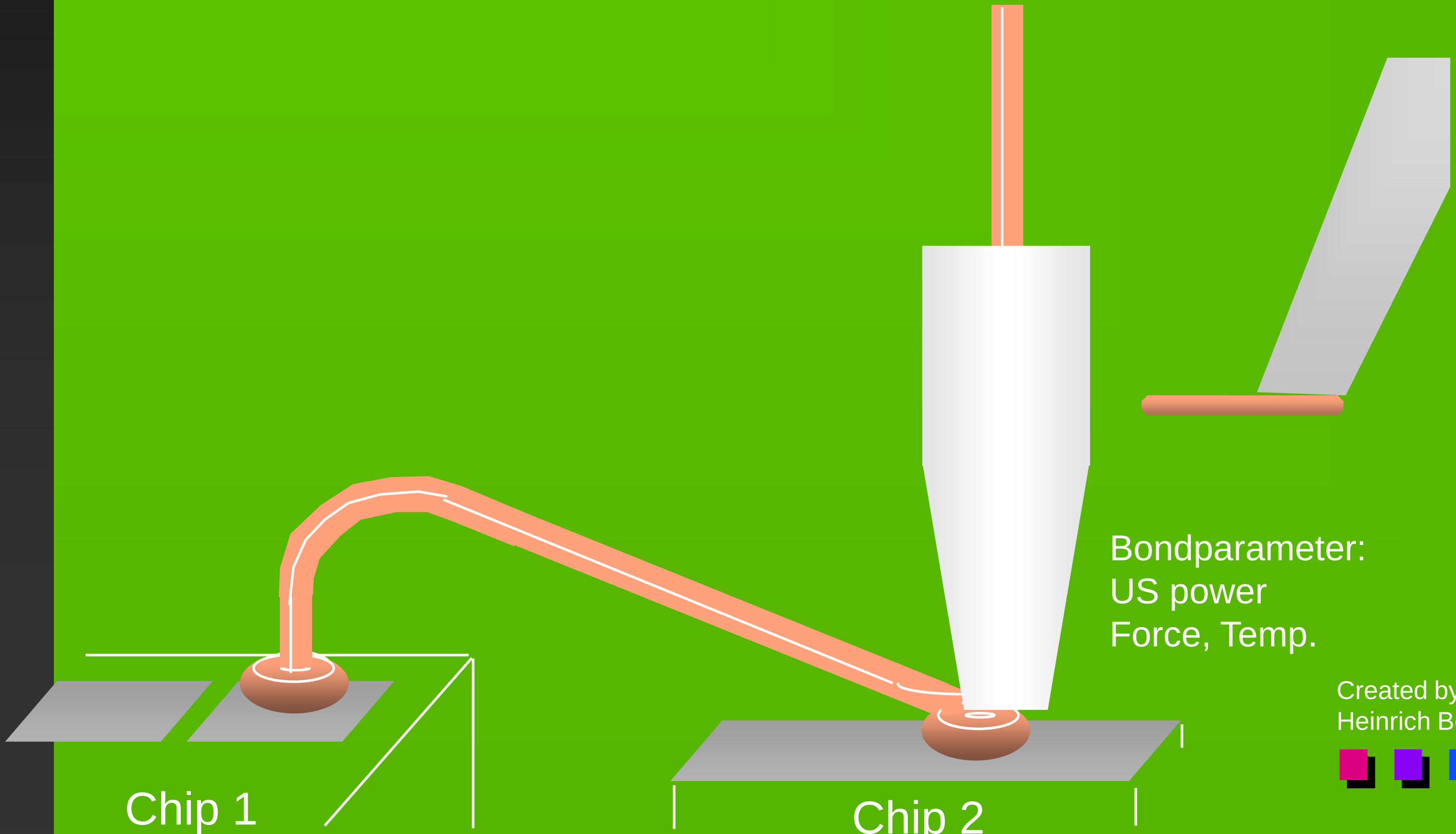

Bondparameter:
US power
Force, Temp.

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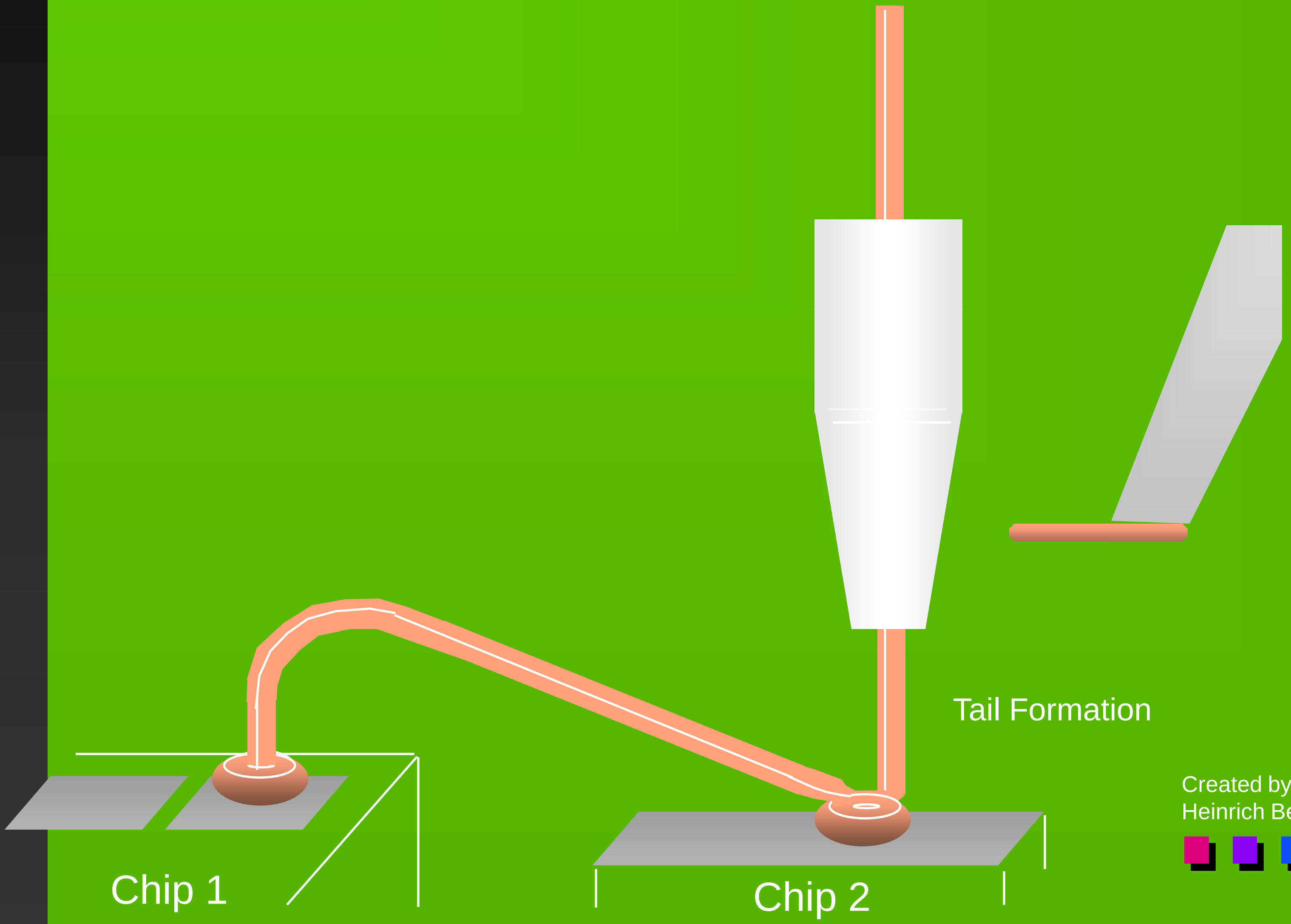

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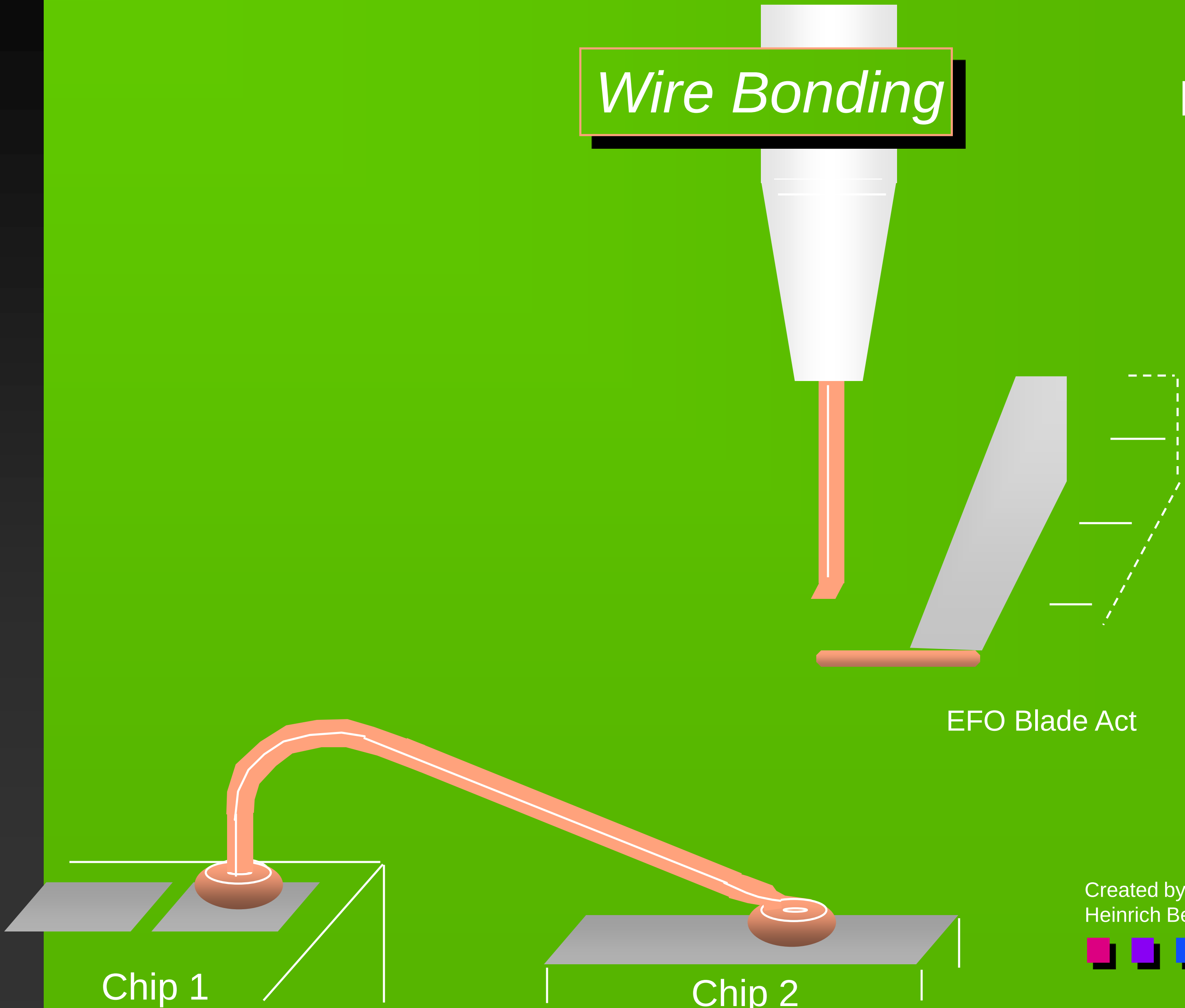

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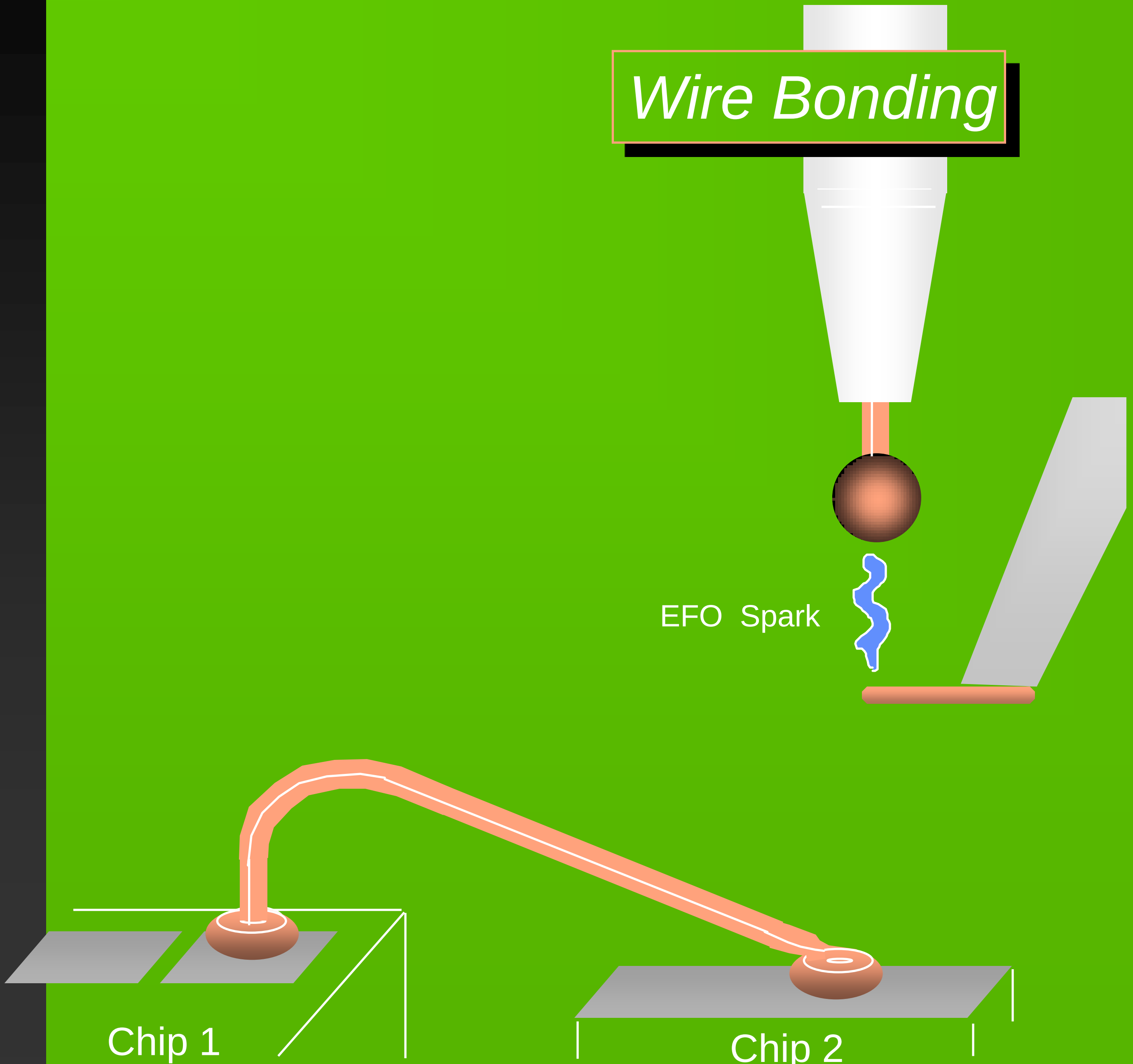

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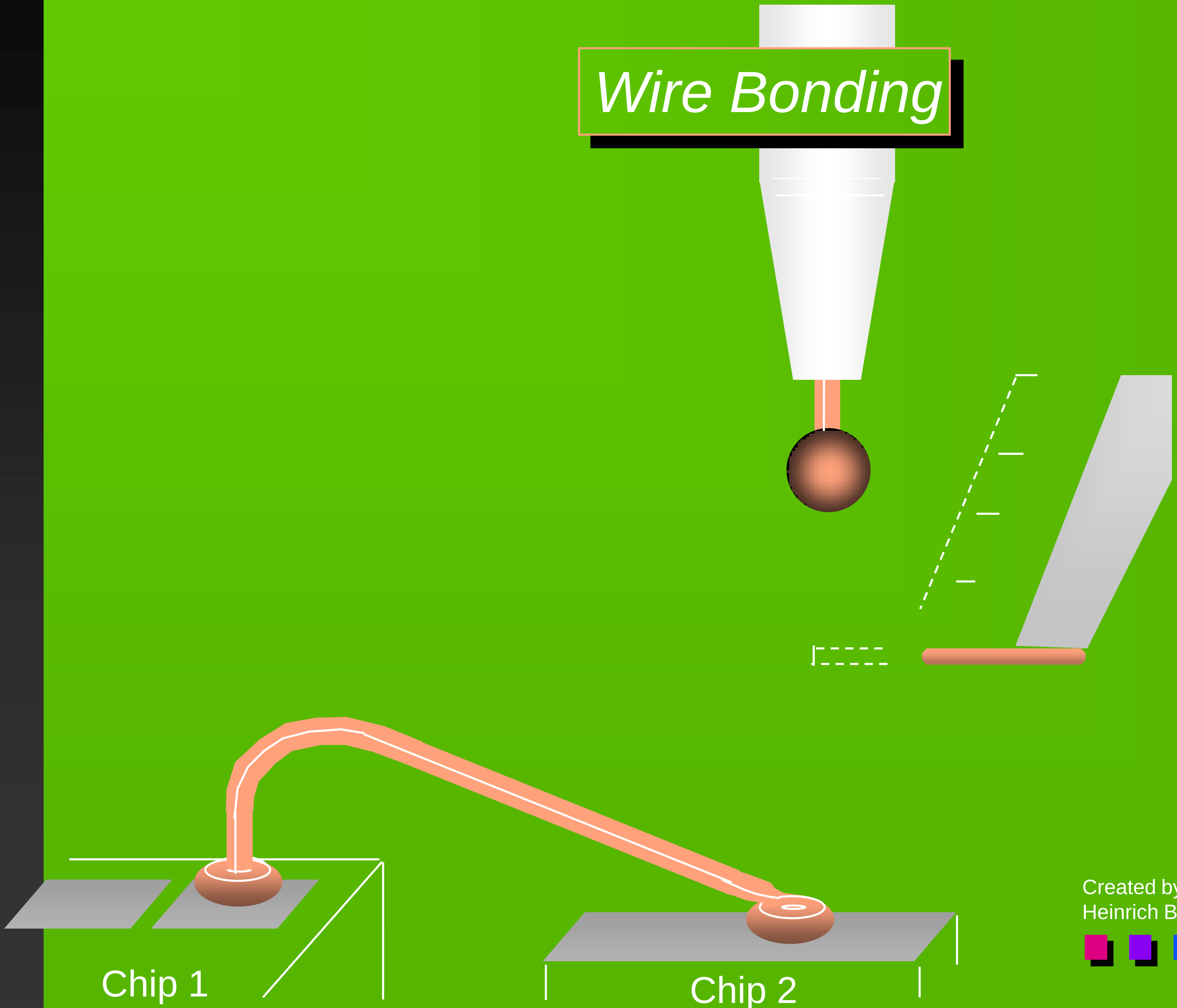

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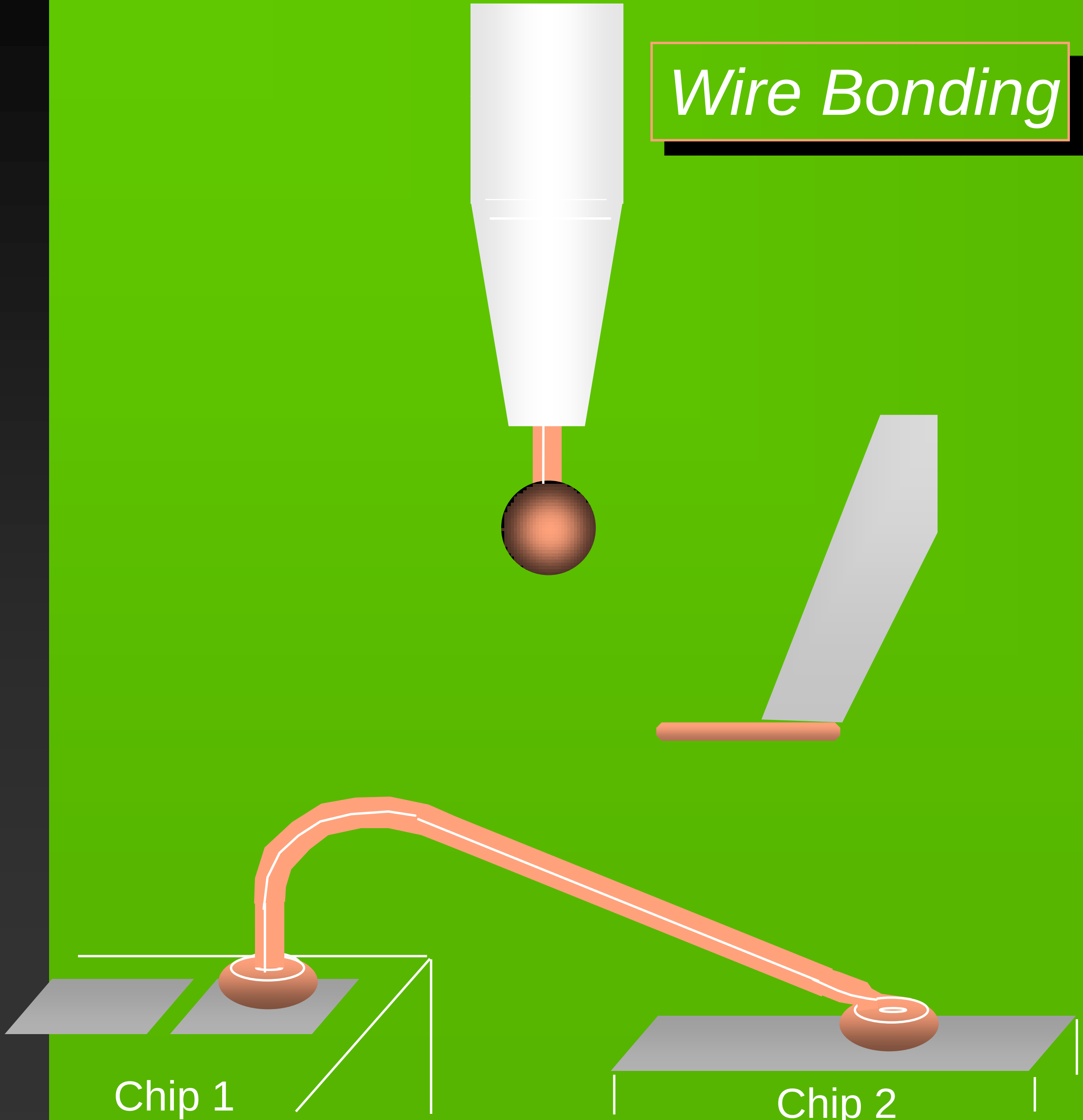

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